

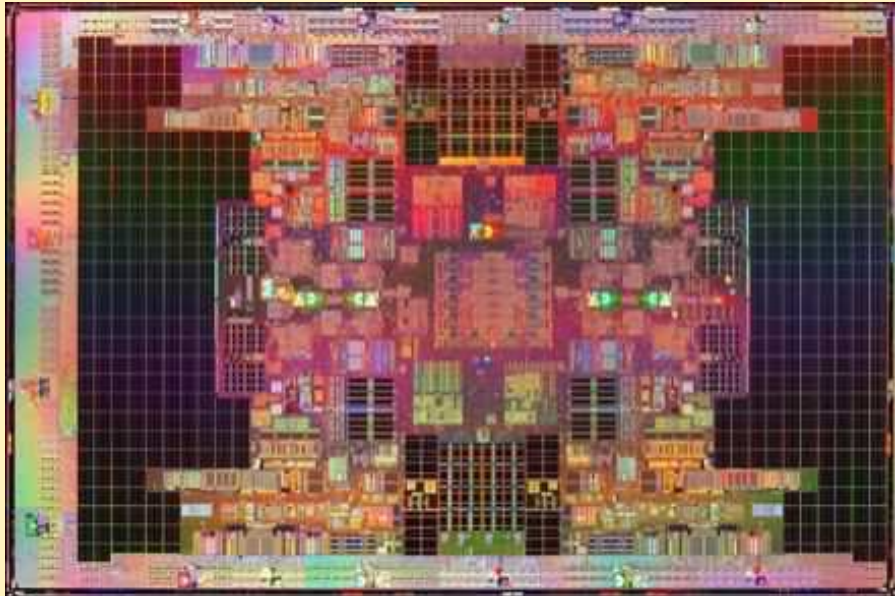
The Rise and Fall of System on Chip

Axel Jantsch

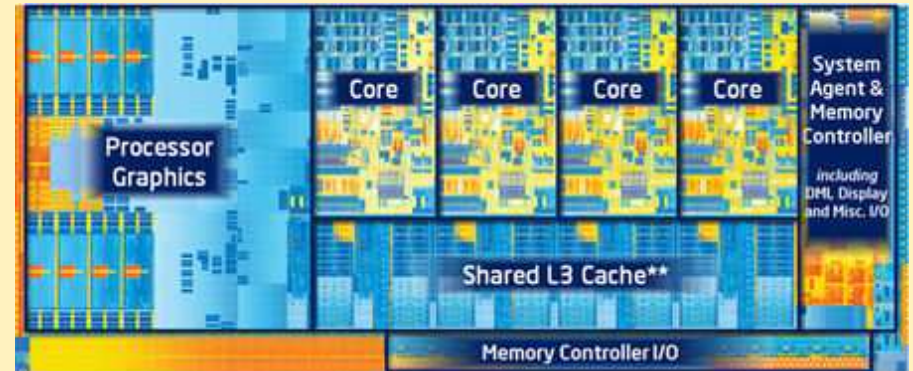
October 25, 2013

What is a System on Chip?

What is a SoC

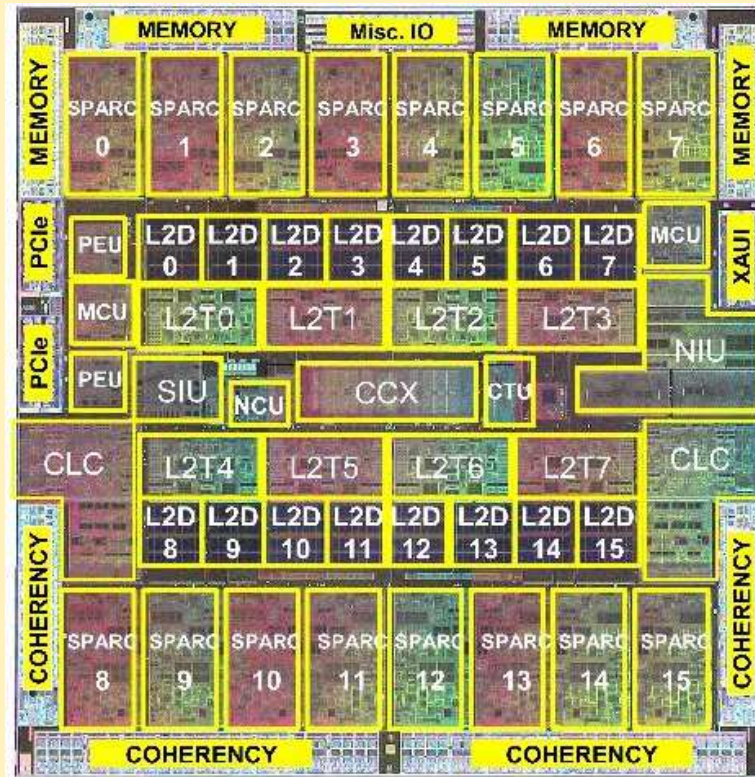


Intel Tukwila:
 $2.046 \cdot 10^9$ Transistors
 $21.5 \times 32.5 \text{mm}^2$ 65nm Technology,
170 W, 2GHz



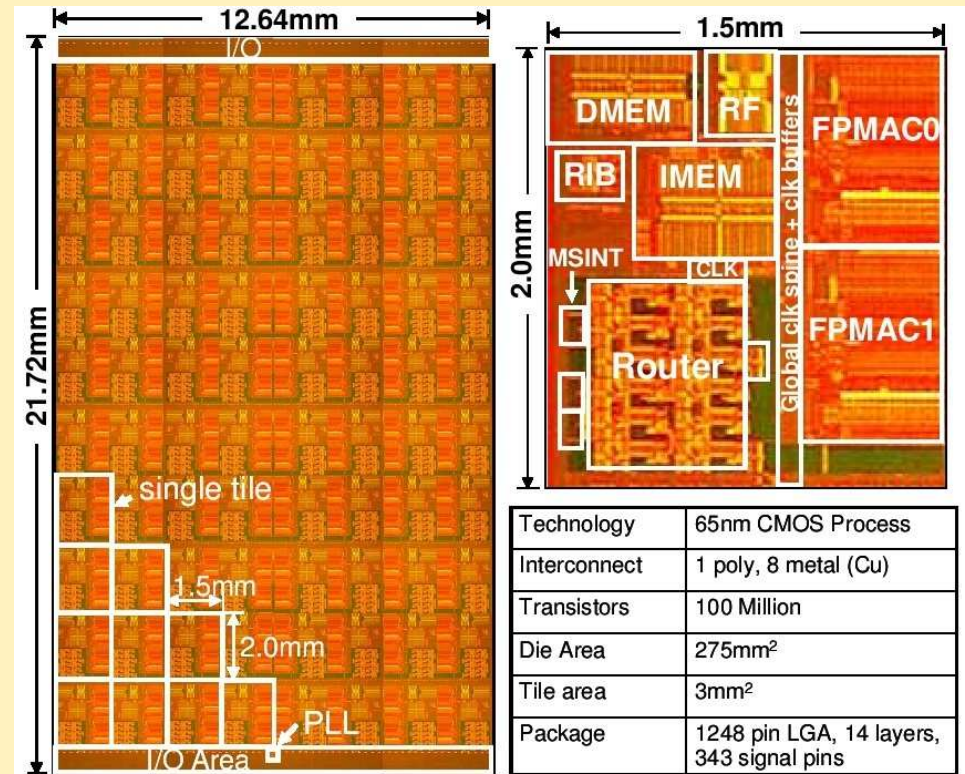
Intel Ivy Bridge:
 $1.4 \cdot 10^9$ Transistors
 160mm^2 22nm Technology,
77 W, 3.9 GHz

What is a SoC



Sun Niagara 3:

$1 \cdot 10^9$ Transistors
 16 cores, 377mm^2 40nm Technology
 1.67 GHz, 60 W



Intel Teraflop:

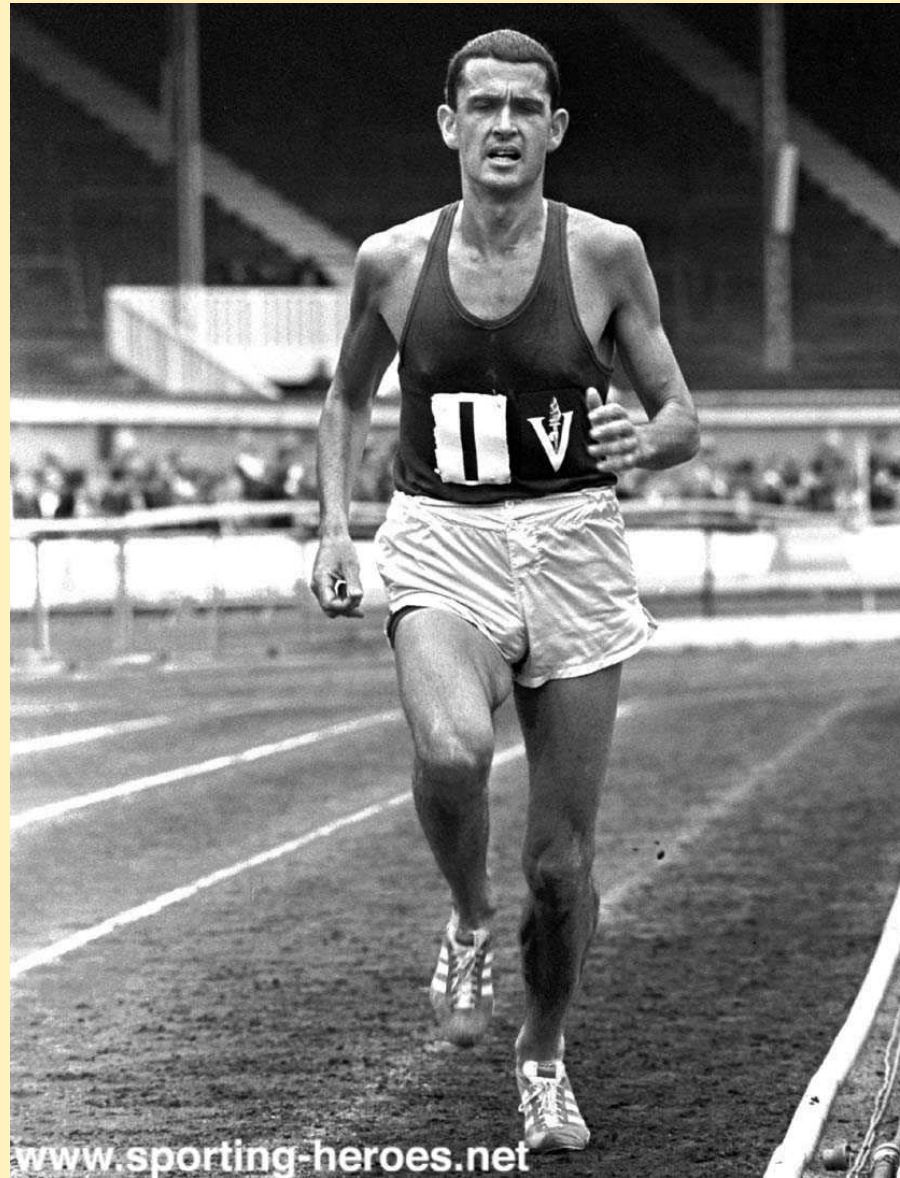
$100 \cdot 10^6$ Transistors
 80 cores, 275mm^2 65nm Technology
 3.67 GHz, 62 W

Moore's Law

1965



1965



Ron Clarke: 28:14.0 world record in 10 000 m

1965



Mika Aaltonen: Turku borne football player

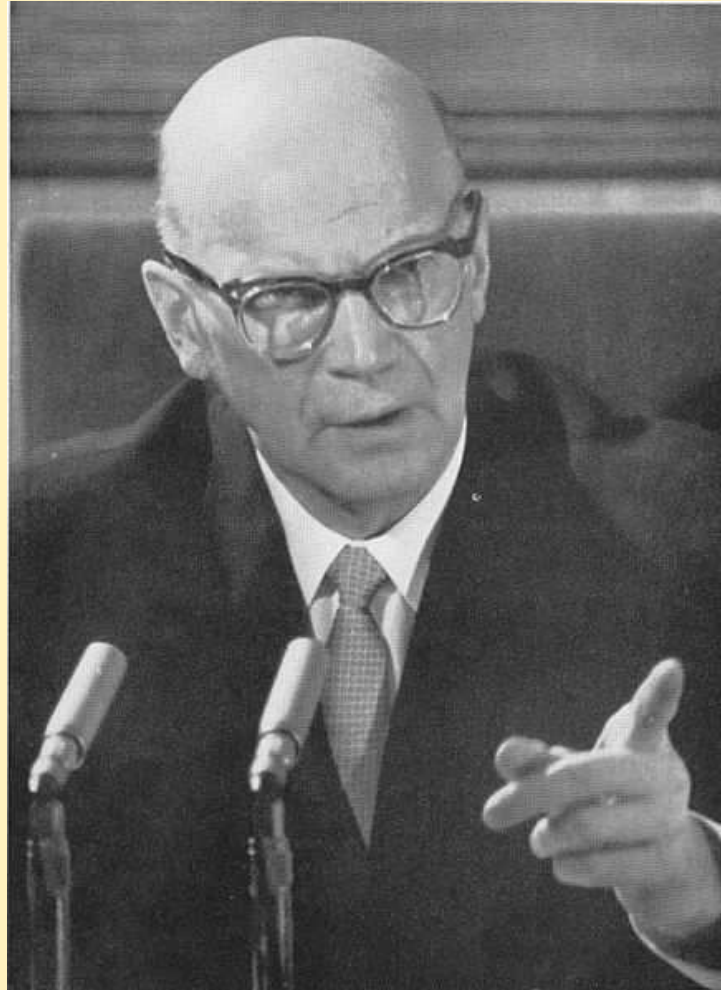
Ron Clarke: 28:14.0 world record in 10 000 m

1965



Rauno Aaltonen: Won European and Finish Rally Championship

1965



Urho Kekkonen: President 1956-82

1965



Tage Erlander: Prime Minister 1946-69

1965



Tage Erlander and Nikita Khrushchev
Tage Erlander: Prime Minister 1946-69

1965



Lyndon B. Johnson: US President 1963-1968

1965



Lyndon B. Johnson signing the immigration bill

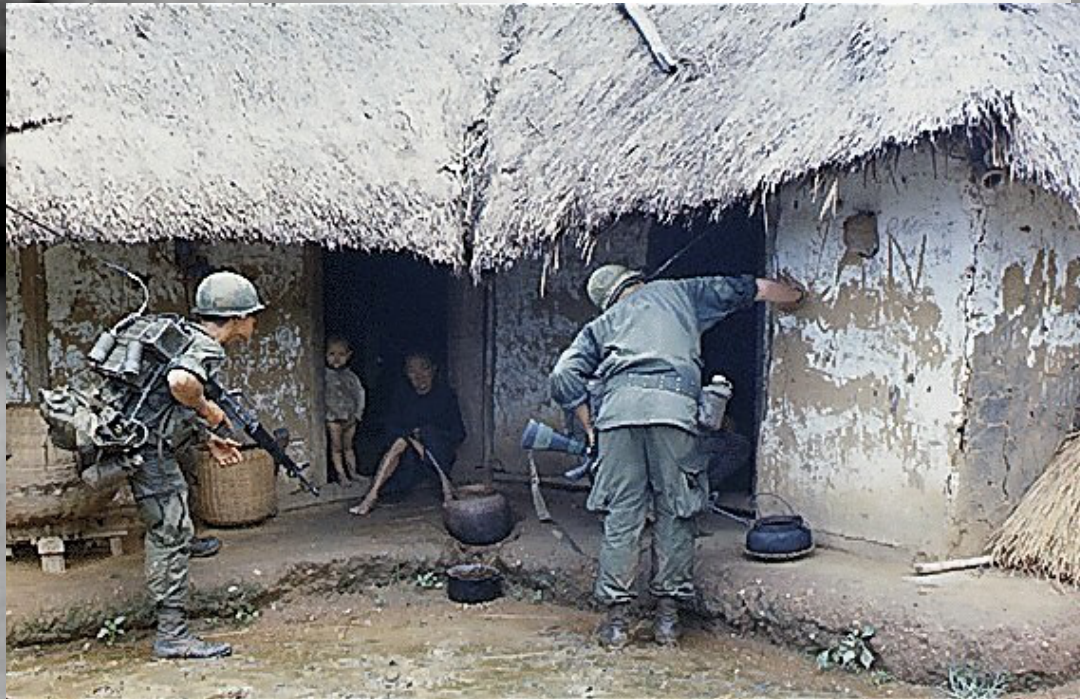
1965



Ly

|

1965



Ly

1965



1965



1965



中国人民解放军是毛泽东思想大学校

Great Leap: 1958-61; Cultural Revolution: 1966-76

1965

打碎旧世界
创立新世界



Grea

76

1965

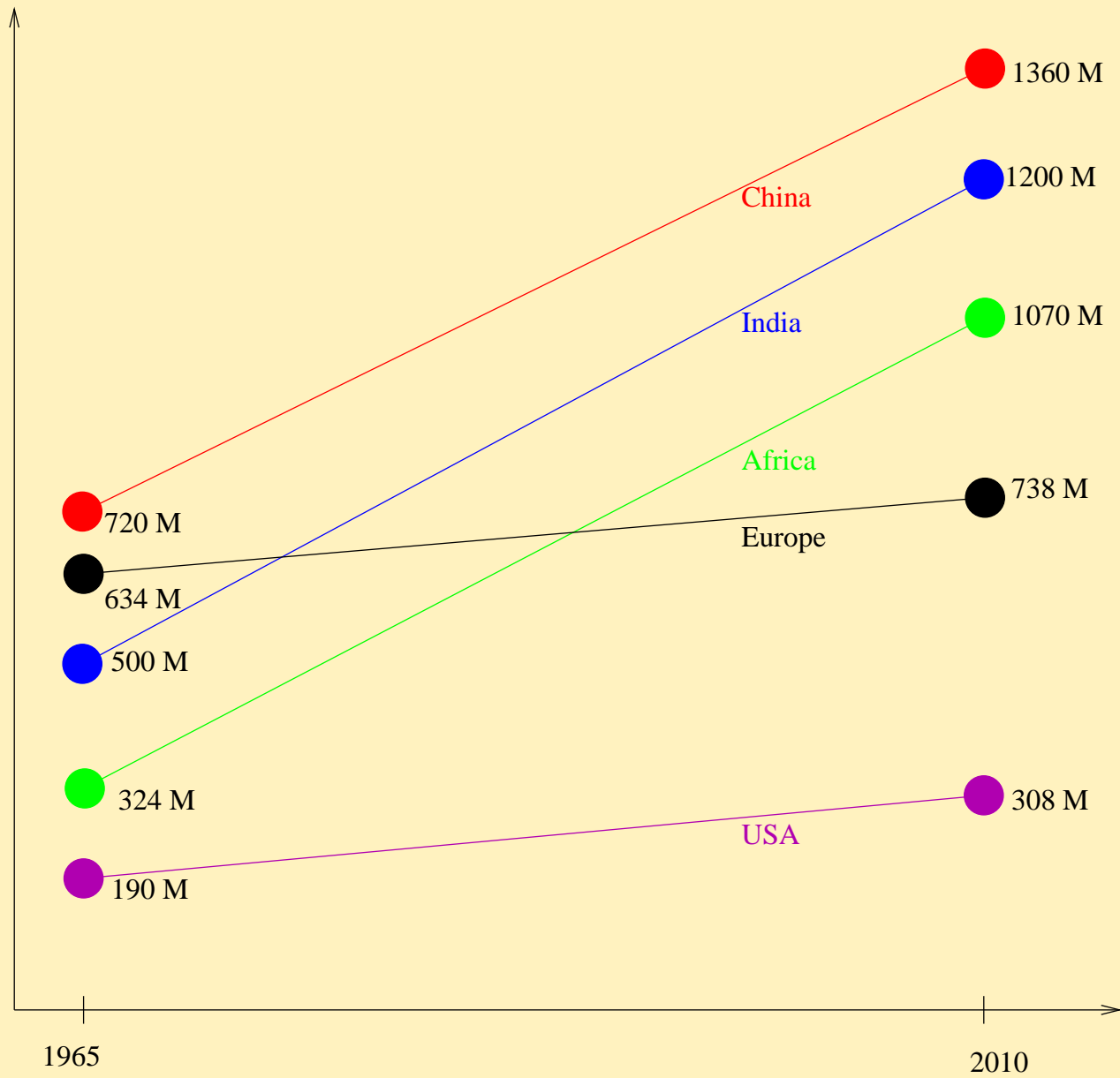
打碎旧世界
创立新世界



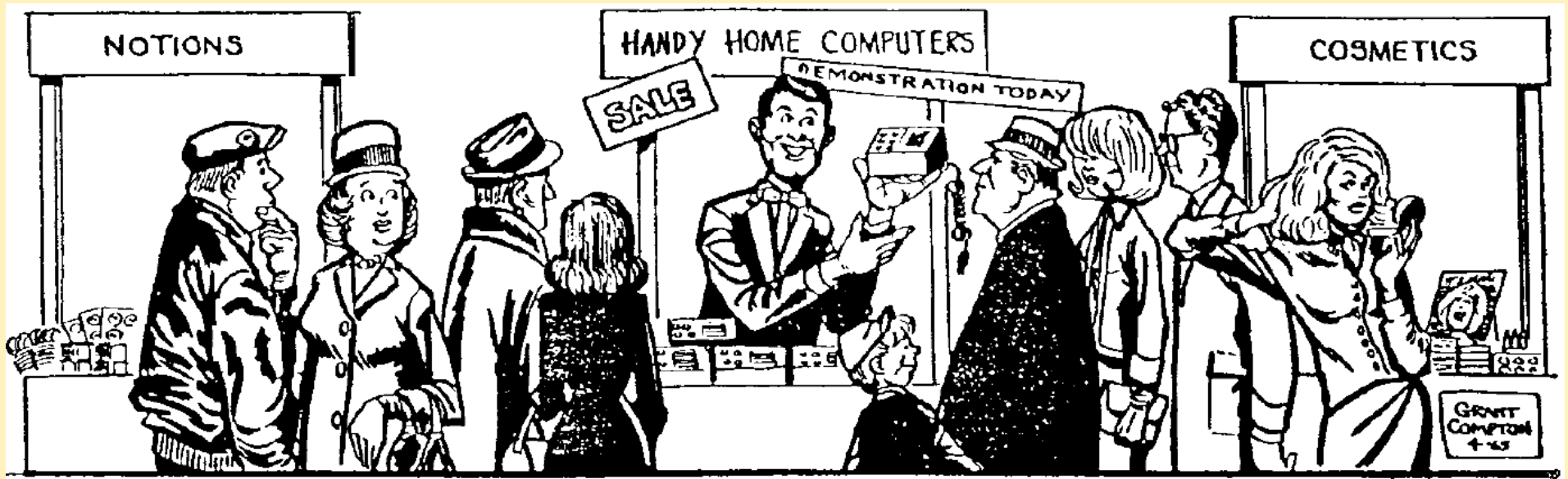
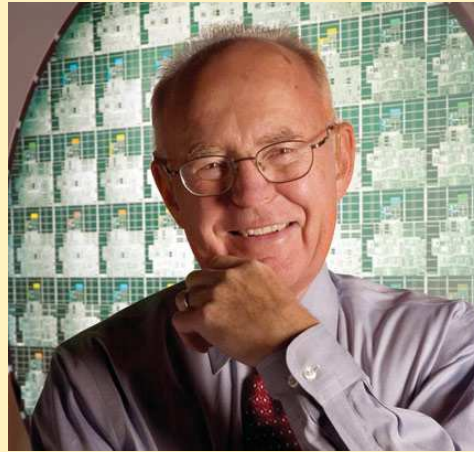
Great

6

1965

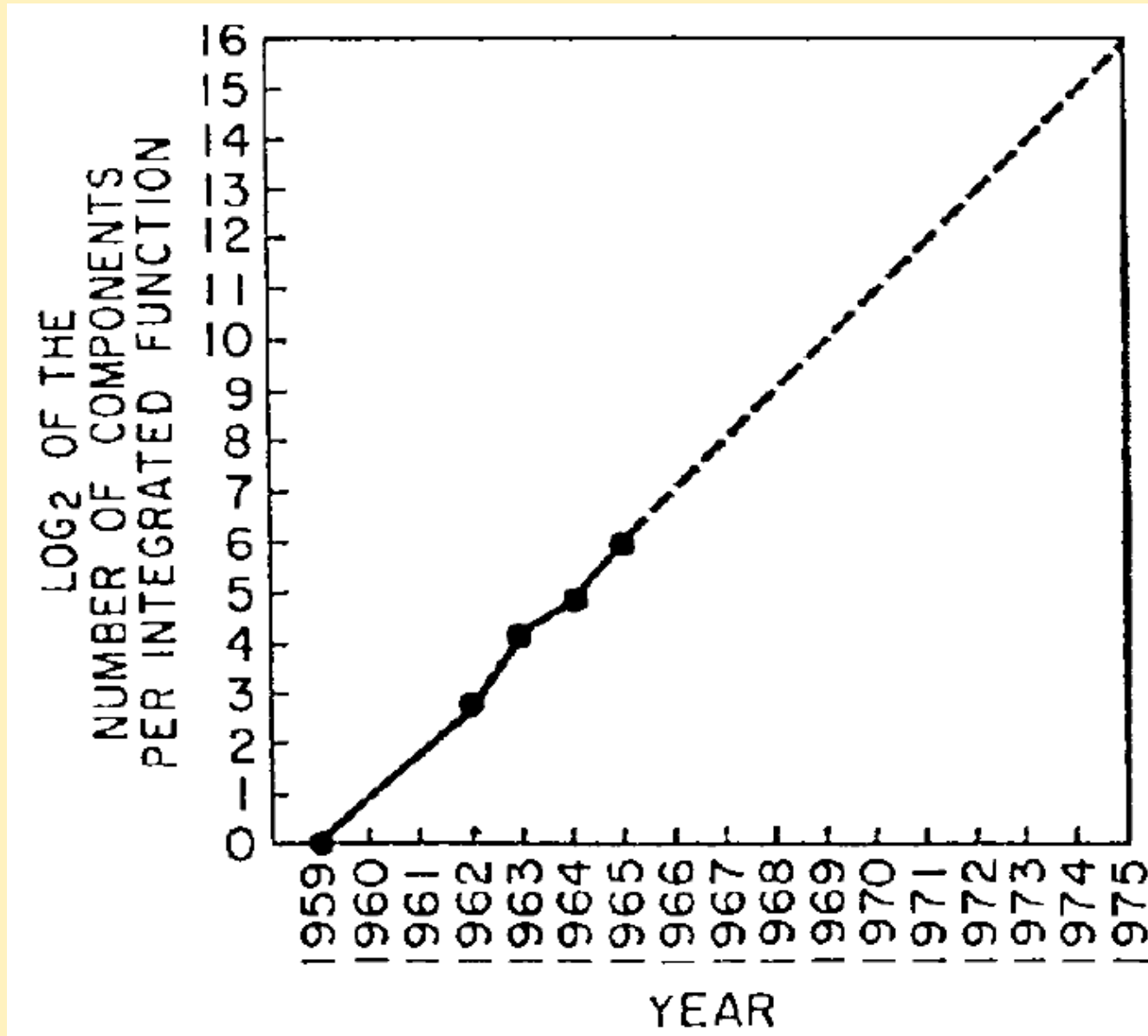


1965



Gordon E. Moore. "Cramming More Components onto Integrated Circuits". In: *Electronics* (1965), pp. 114–117

Moore's Law



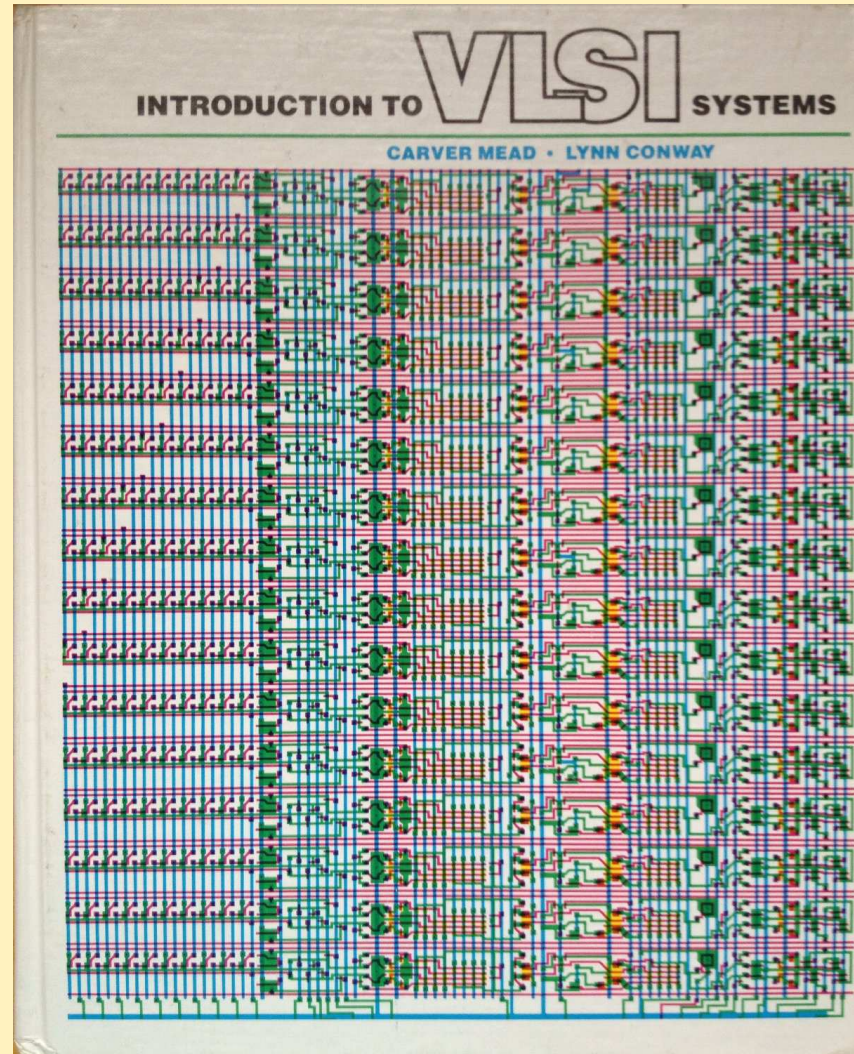
Gordon E. Moore. "Cramming More Components onto Integrated Circuits". In: *Electronics* (1965), pp. 114–117

Main Deflection Points

Mead-Conway Revolution



Carver Mead

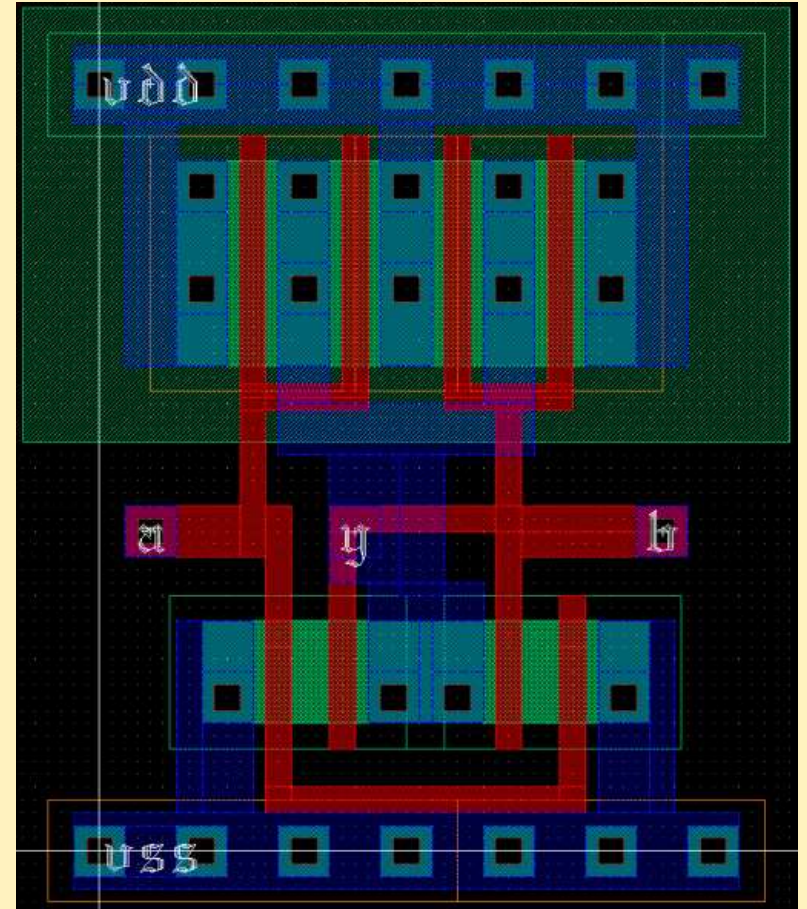
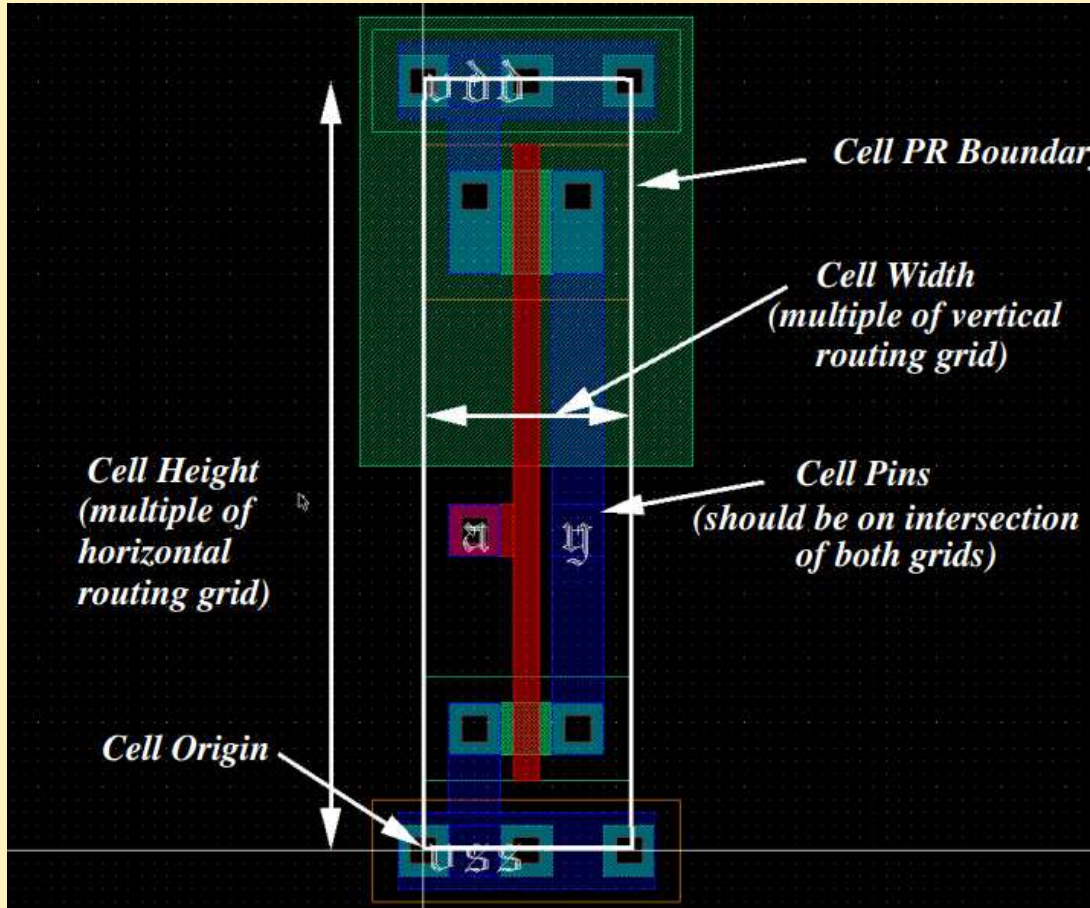


Lynn Conway

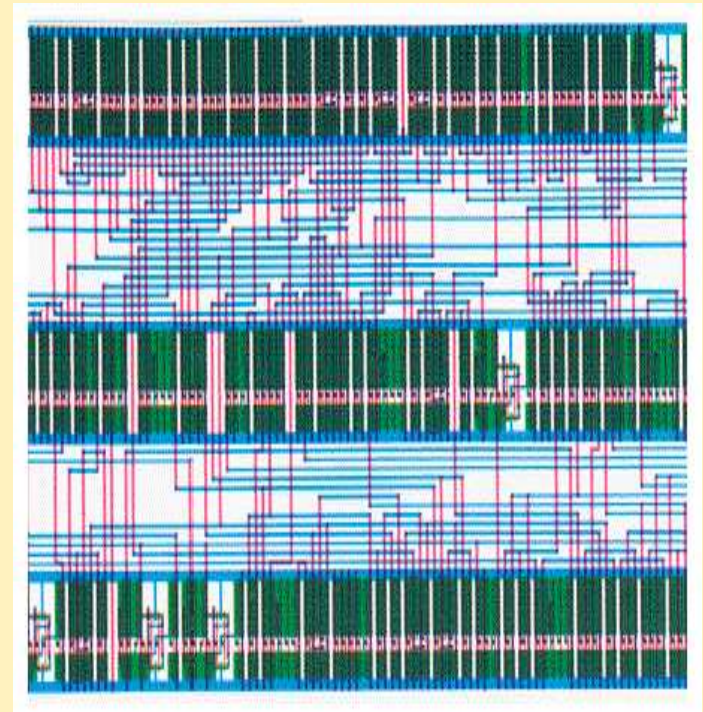
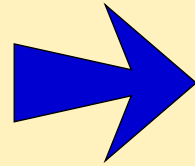
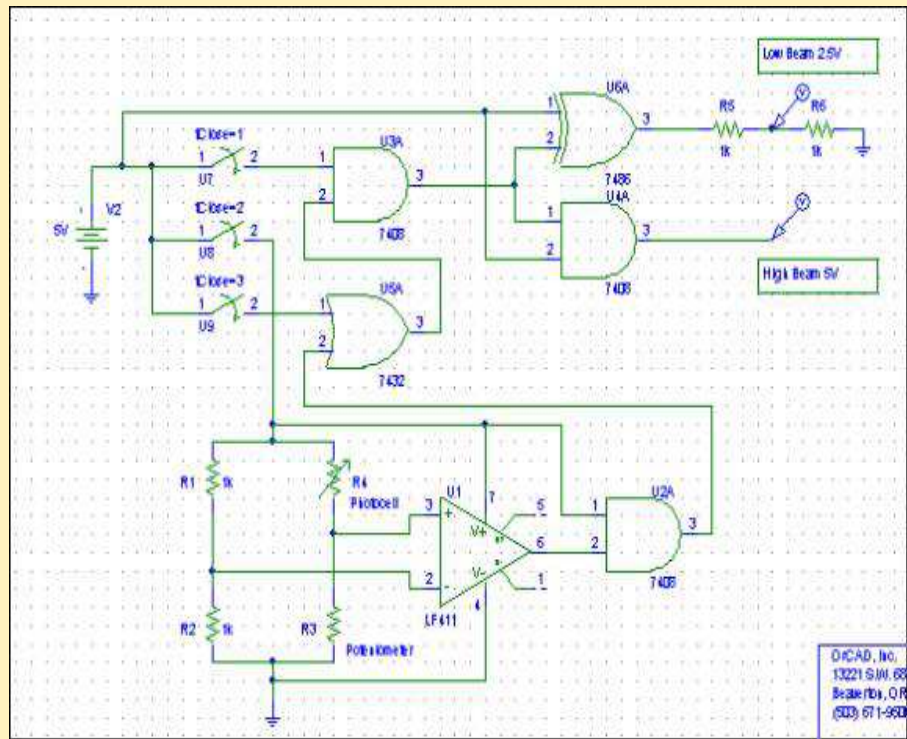
Carver Mead and Lynn Conway. *Introduction to VLSI Systems*. Addison-Wesley, 1980

1980 - 20 000 Transistors

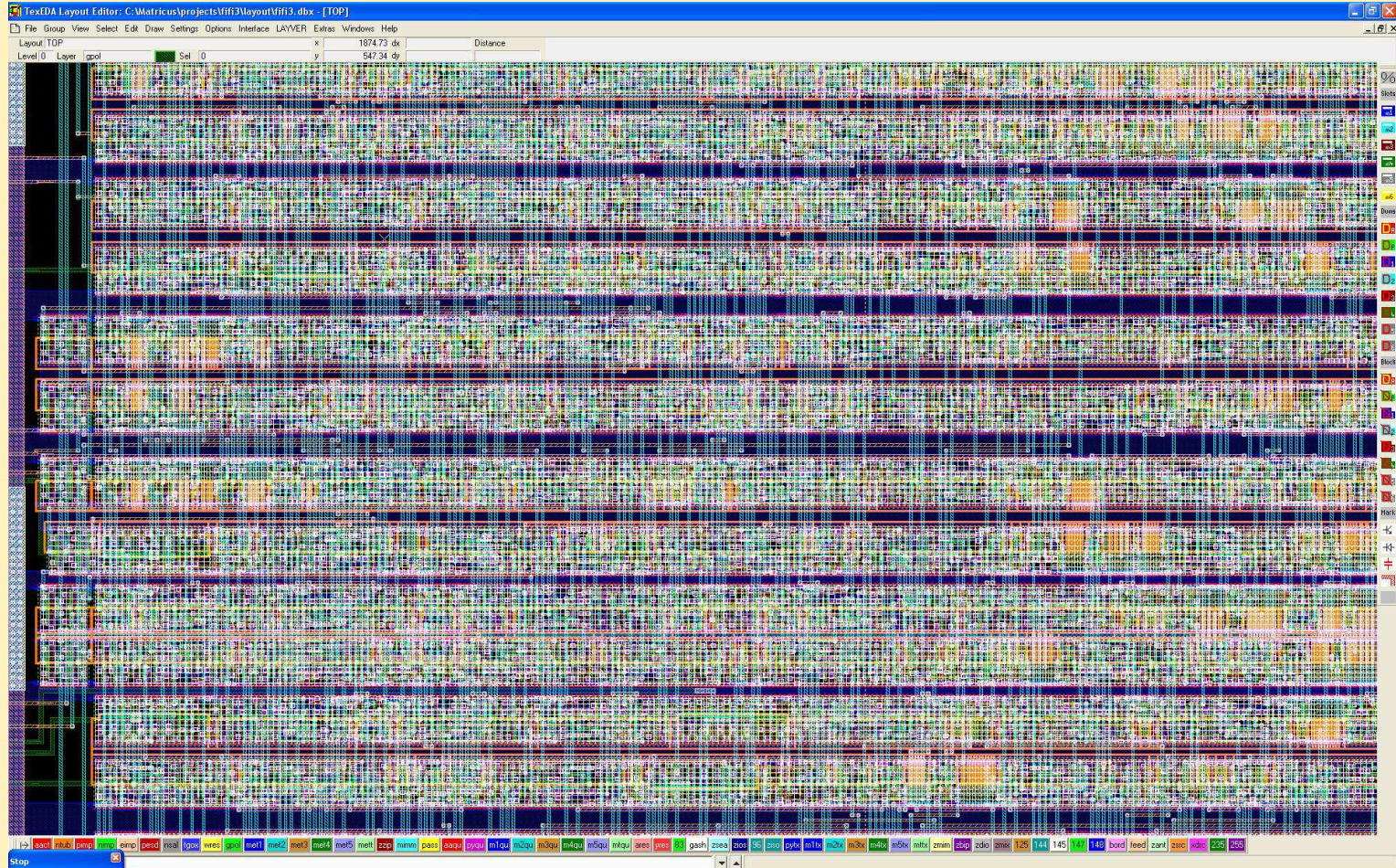
Standard Cells



Standard Cells



Standard Cells



Logic Synthesis

	y	
	0	1
x	0	0
1	0	1

	y	
	0	1
x	0	1
1	1	1

	y	
	0	1
x	0	1
1	0	1

	y	
	0	1
x	0	1
1	1	0

Figure 1. Truth tables

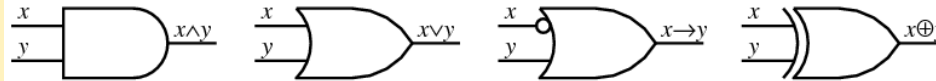


Figure 2. Logic gates

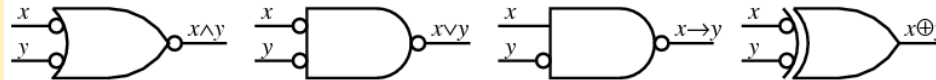


Figure 3. De Morgan equivalents



Figure 4. Venn diagrams

Logic Minimization Algorithms for VLSI Synthesis

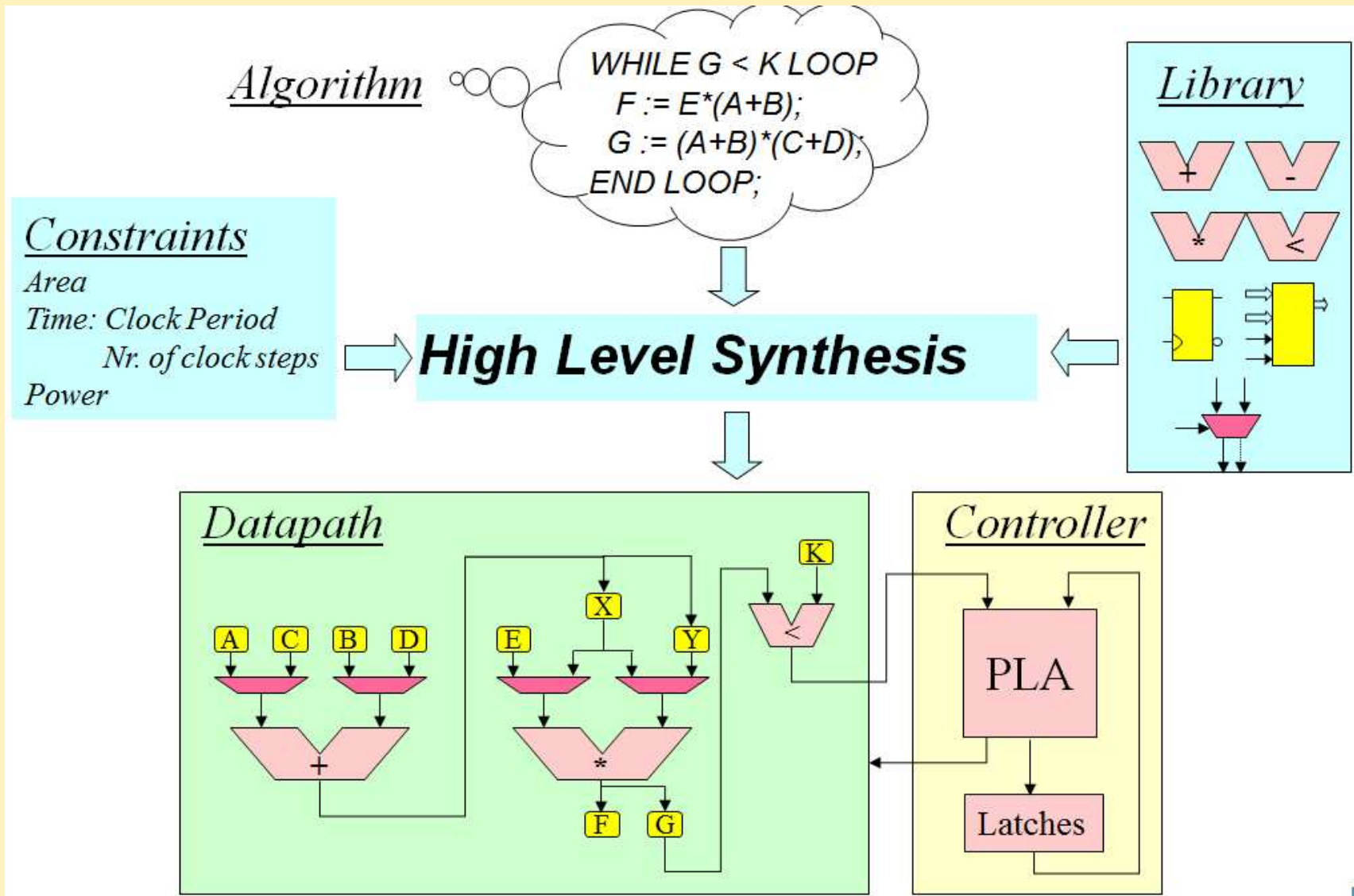
Robert K. Brayton
 Gary D. Hachtel
 Curtis T. McMullen
 Alberto L. Sangiovanni-Vincentelli



Kluwer Academic Publishers

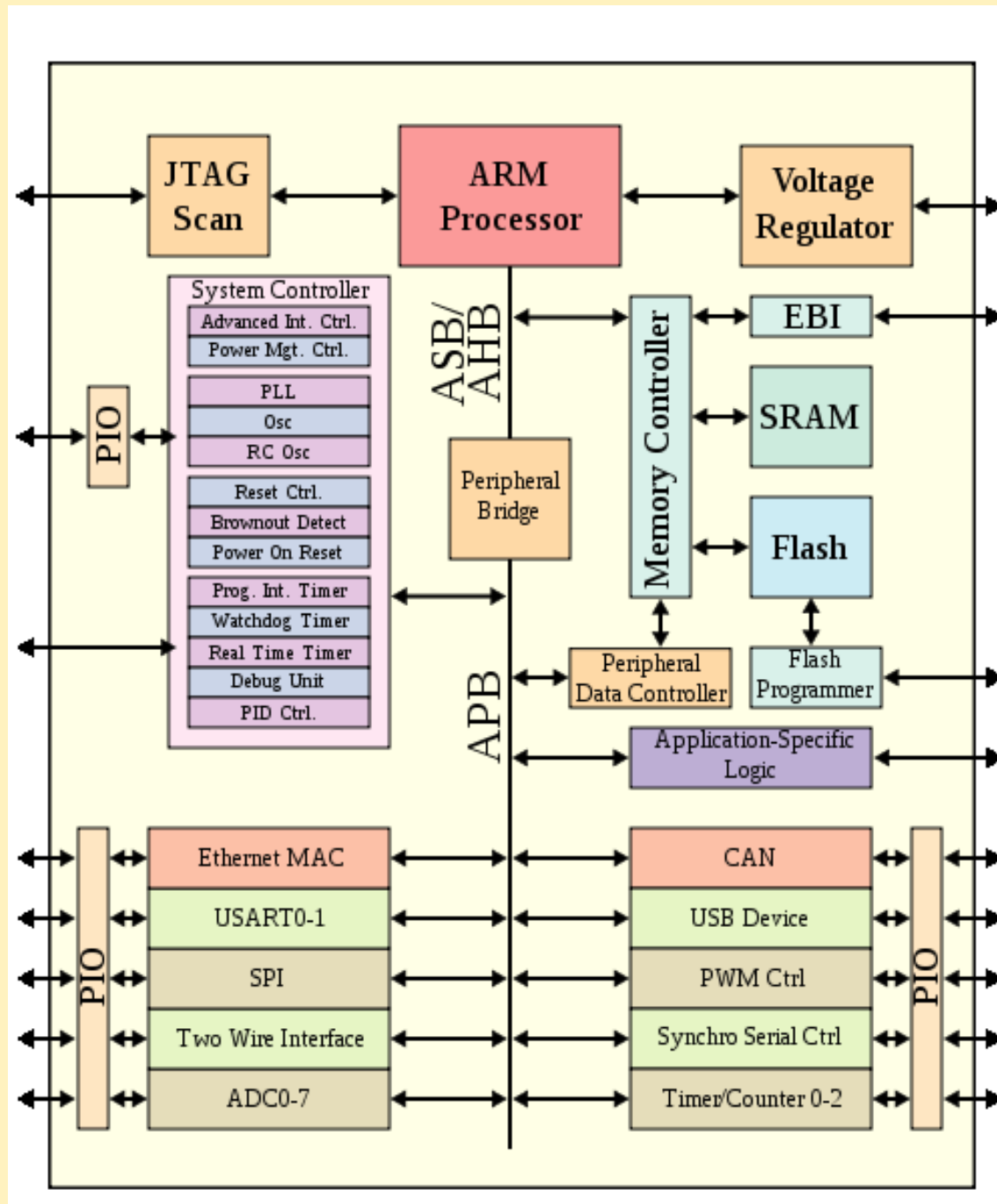
Robert K. Brayton, Gary D. Hachtel, Curtis T. McMullen, and Alberto L. Sangiovanni-Vincentelli. *Logic Minimization Algorithms for VLSI Synthesis*. Kluwer Academic Publisher, 1984

High Level Synthesis

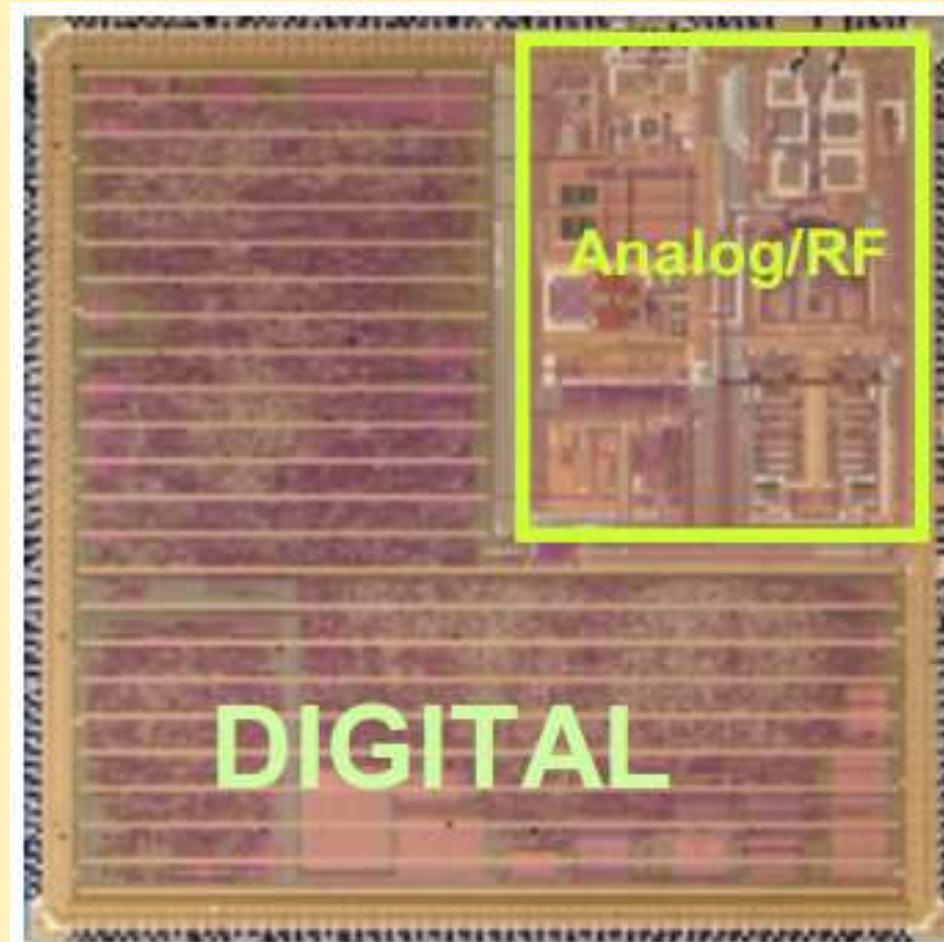


1990 - 1 000 000 Transistors

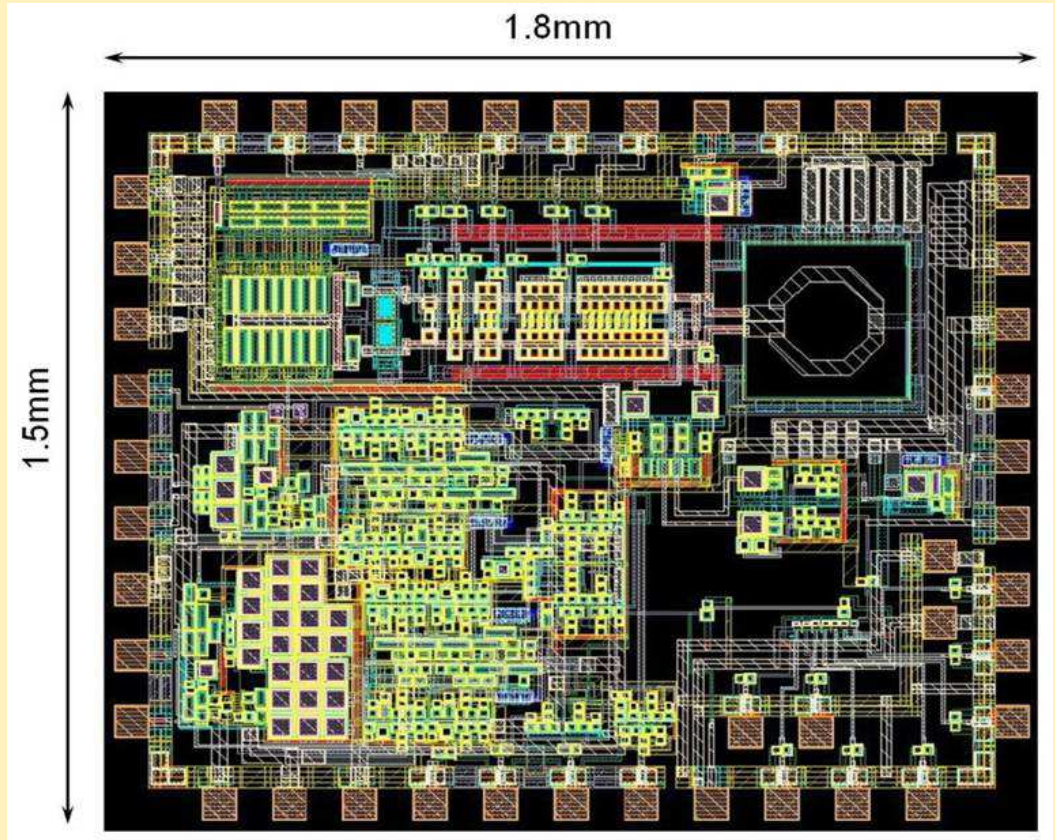
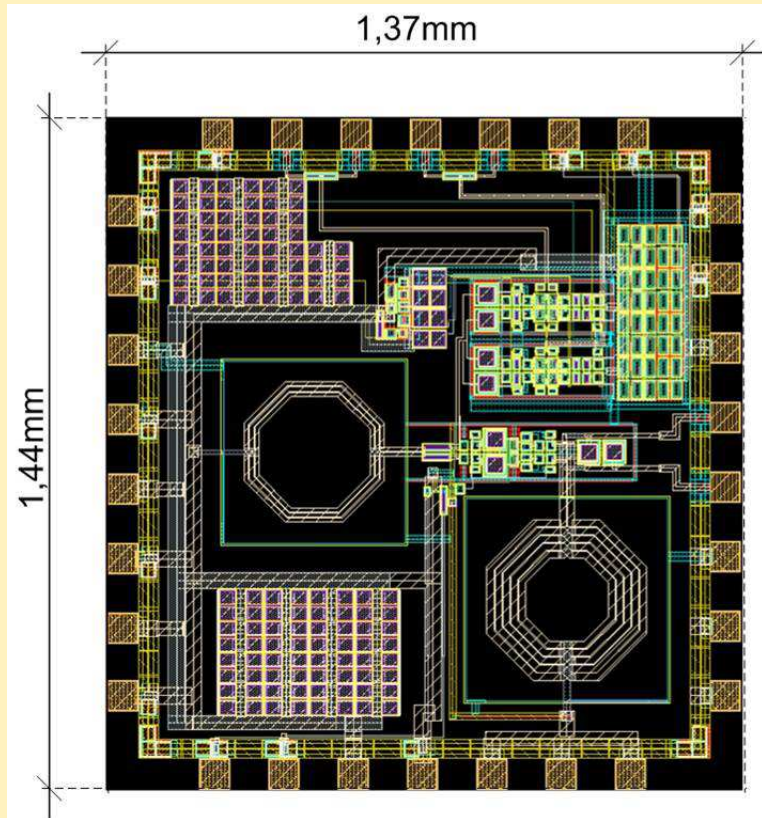
Emergence of SoC



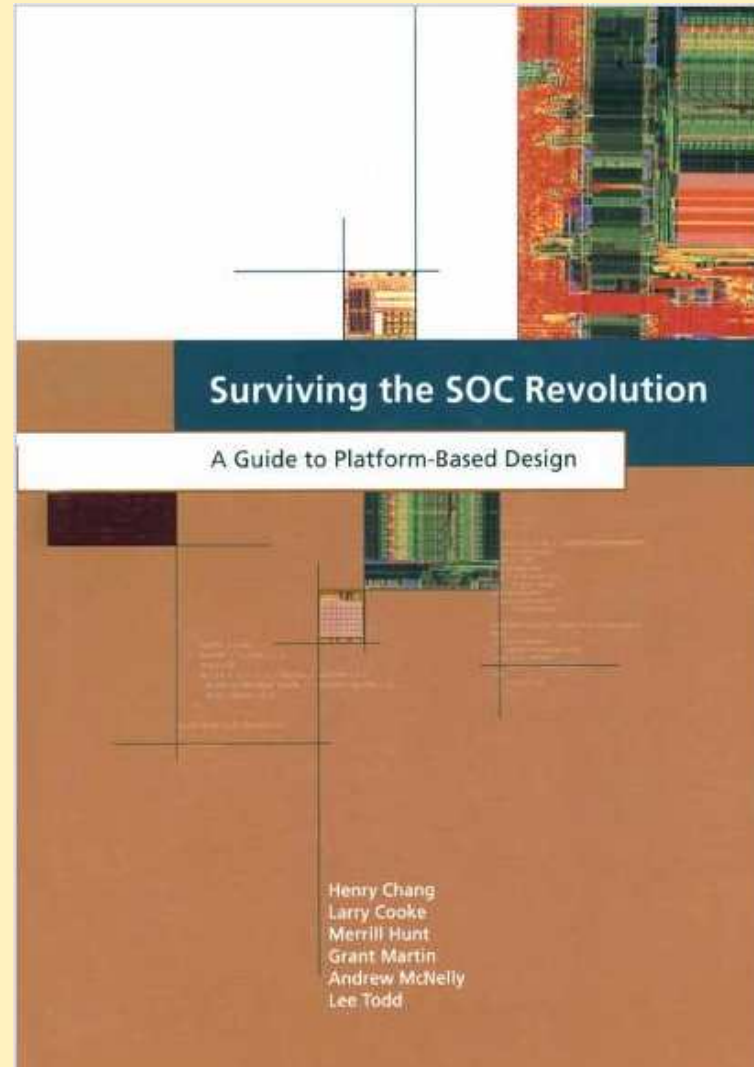
Emergence of SoC



Emergence of SoC

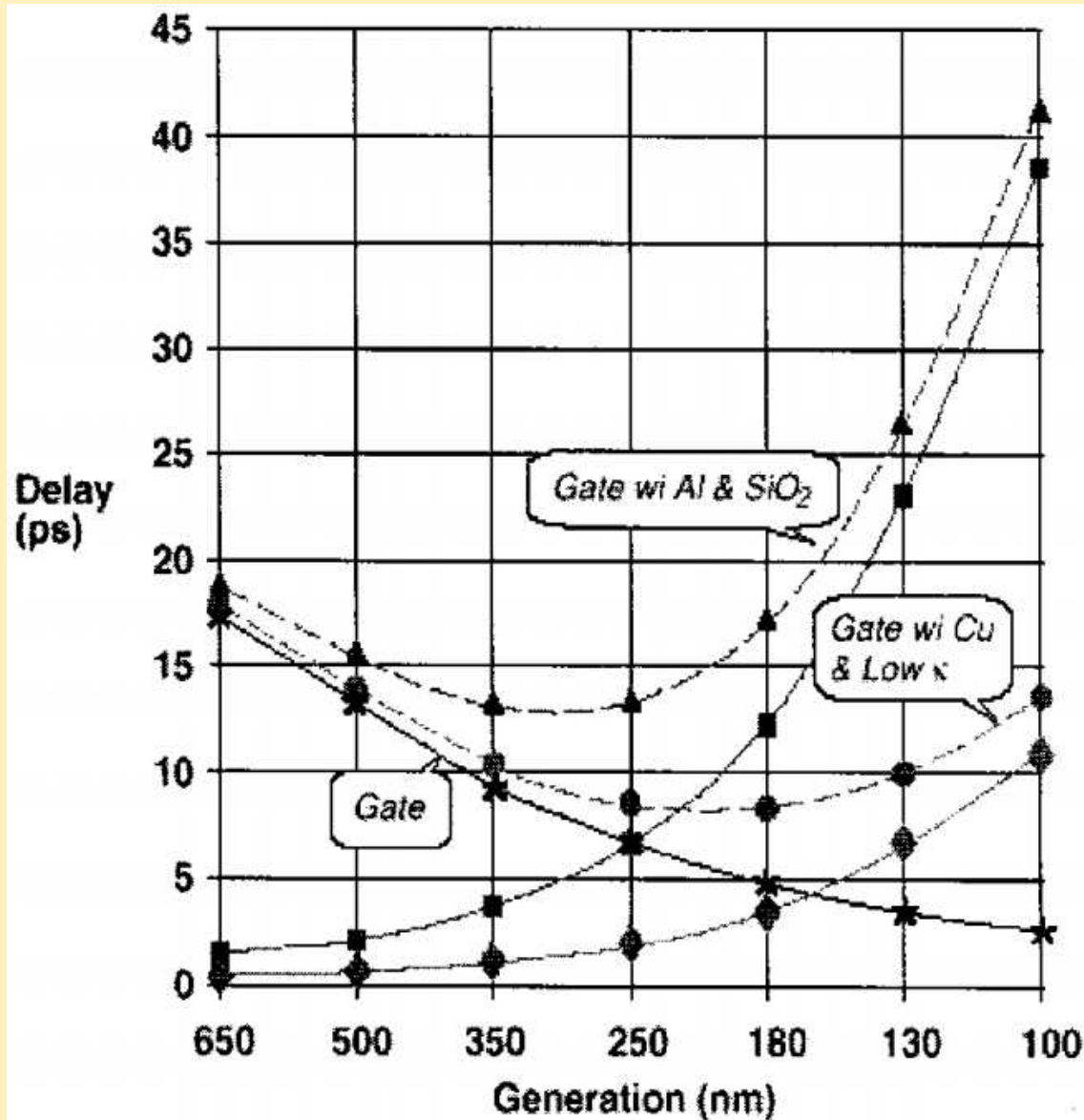


Emergence of SoC

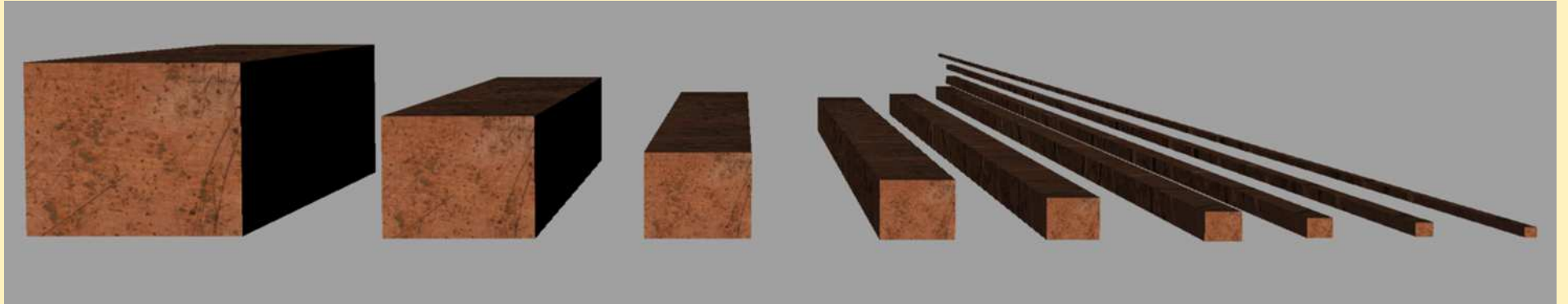


2000 - 20 000 000 Transistors

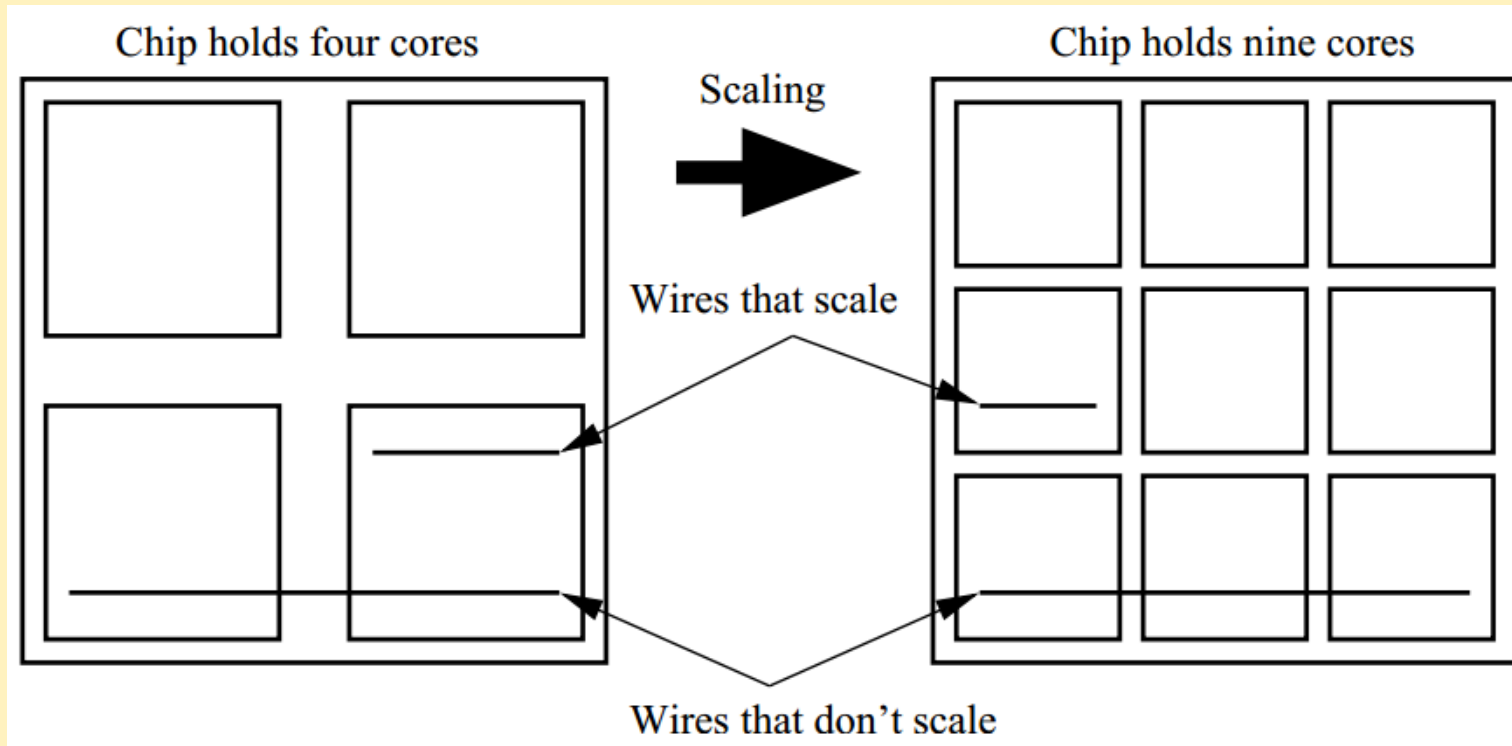
Wires Make Trouble



Wires Make Trouble

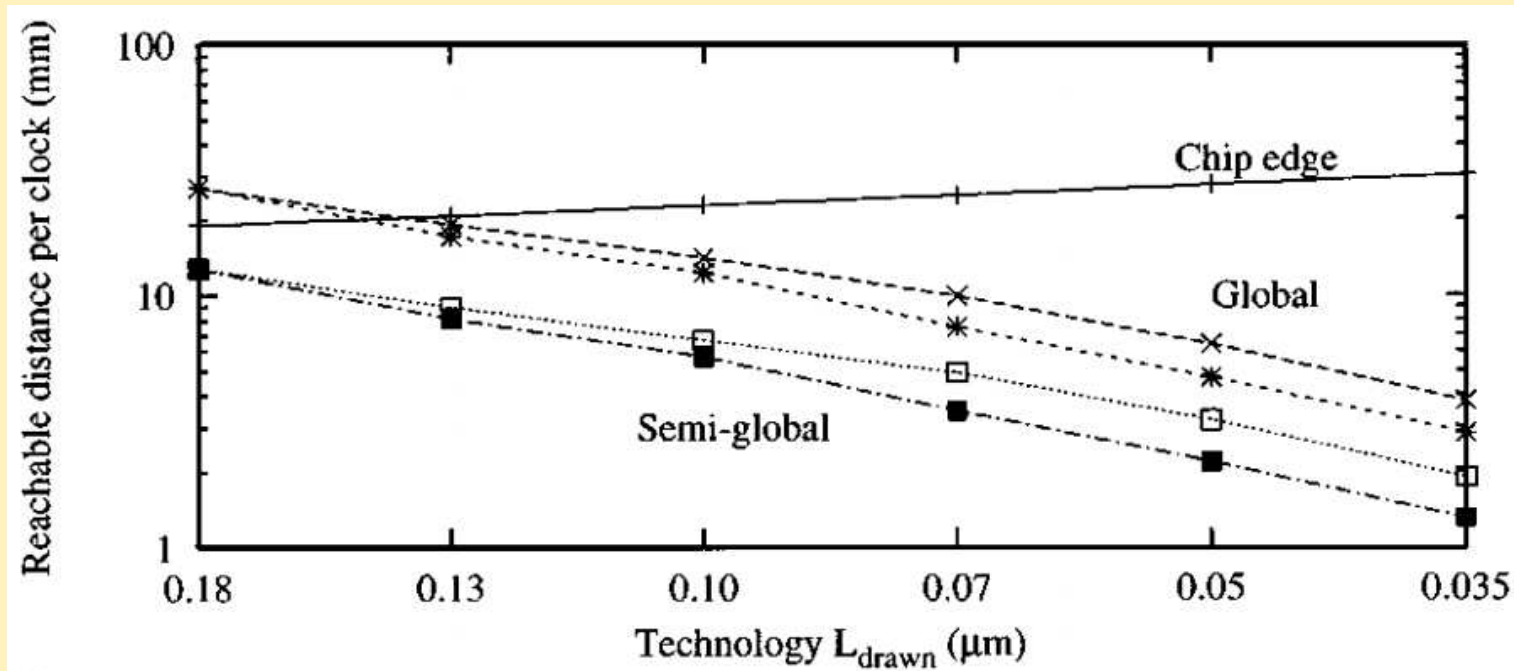


Wires Make Trouble



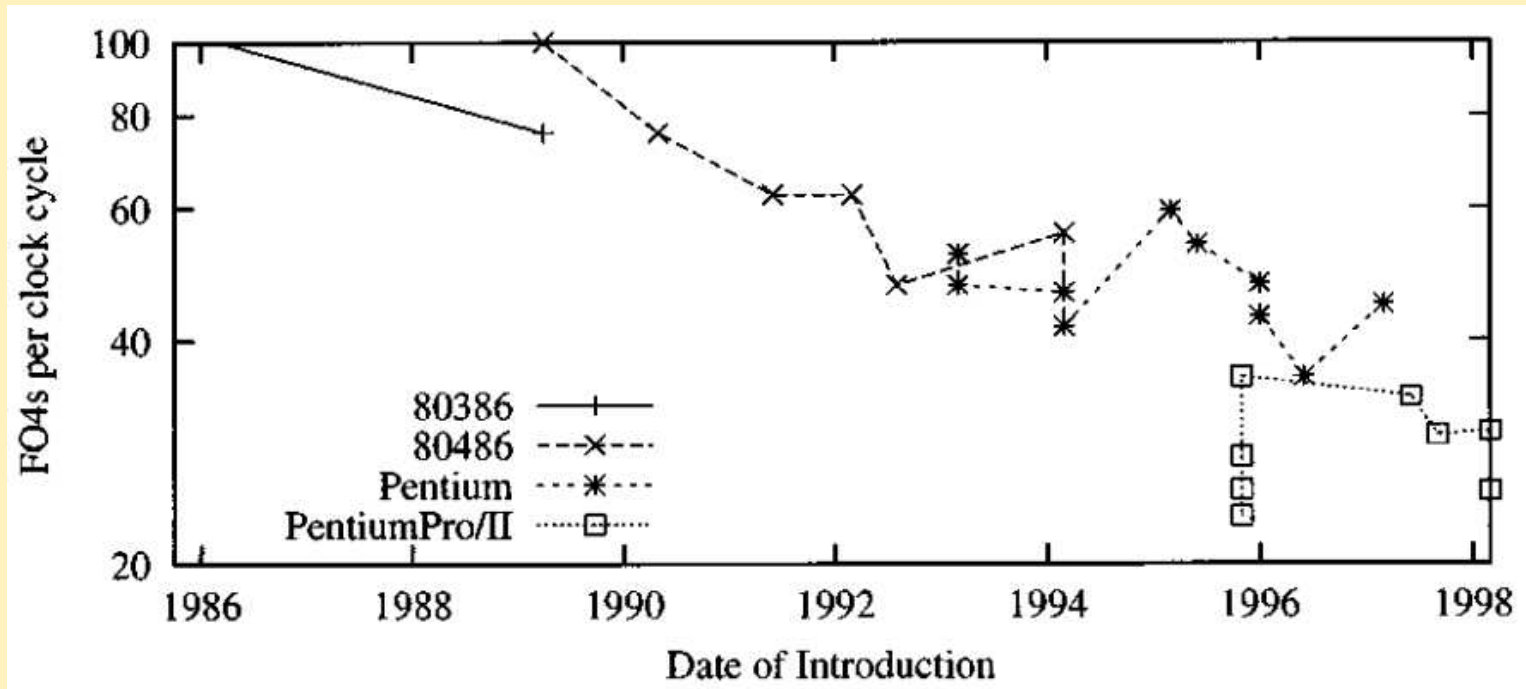
Ron Ho. "On-chip wires: Scaling and efficiency". PhD thesis. Stanford University, 2003

Wires Make Trouble



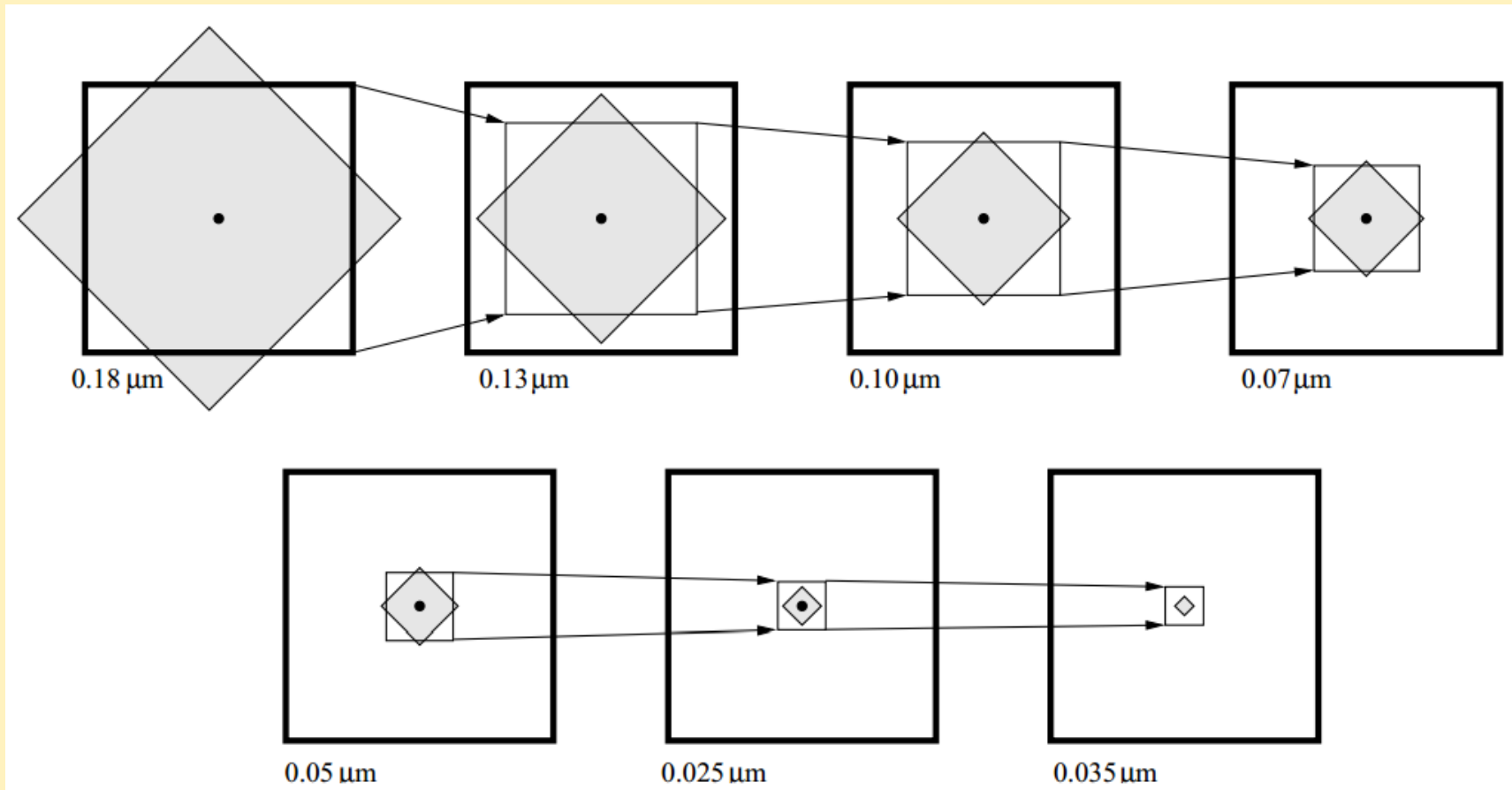
Ron Ho. "On-chip wires: Scaling and efficiency". PhD thesis. Stanford University, 2003

Wires Make Trouble



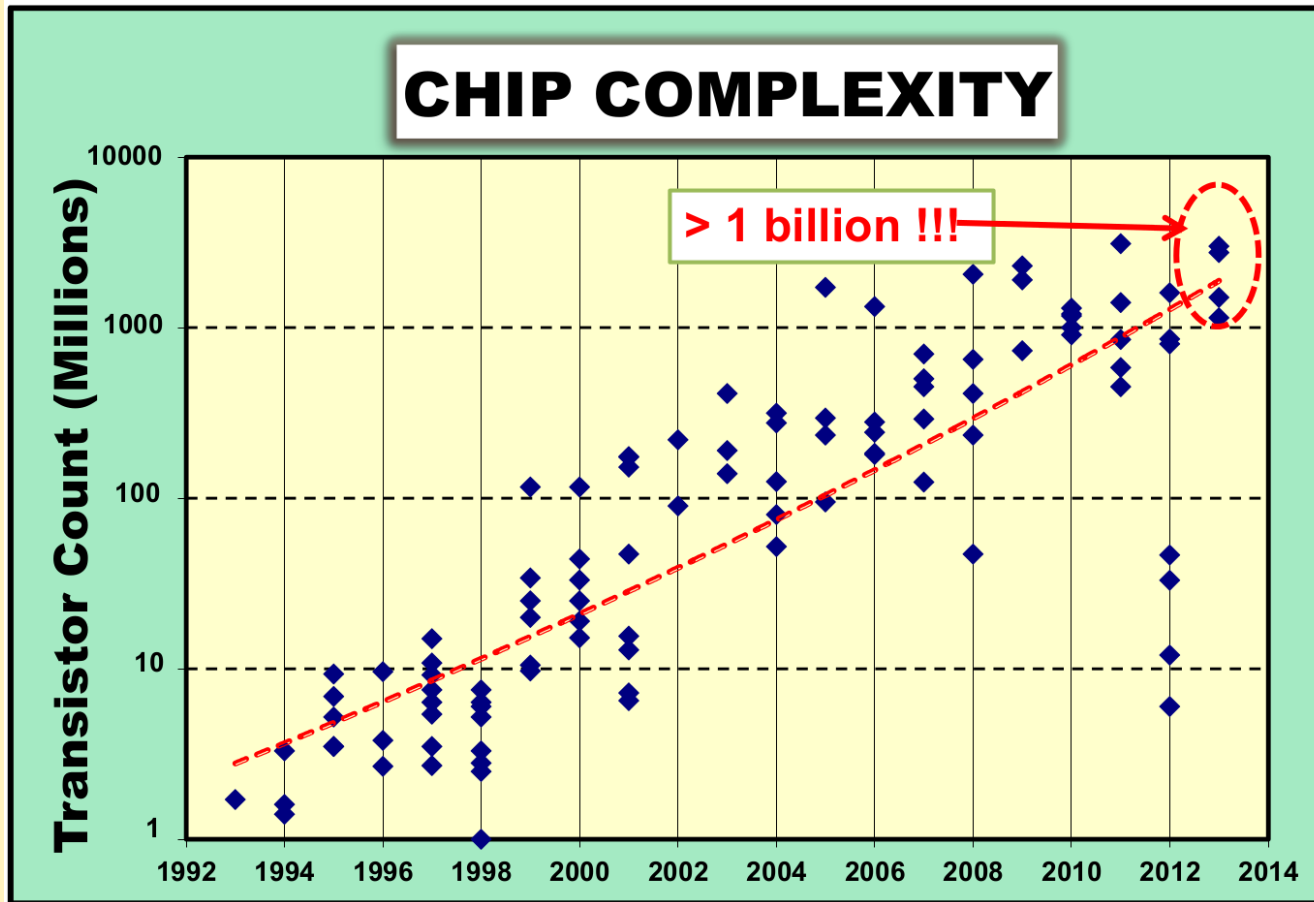
Ron Ho. "On-chip wires: Scaling and efficiency". PhD thesis. Stanford University, 2003

Wires Make Trouble



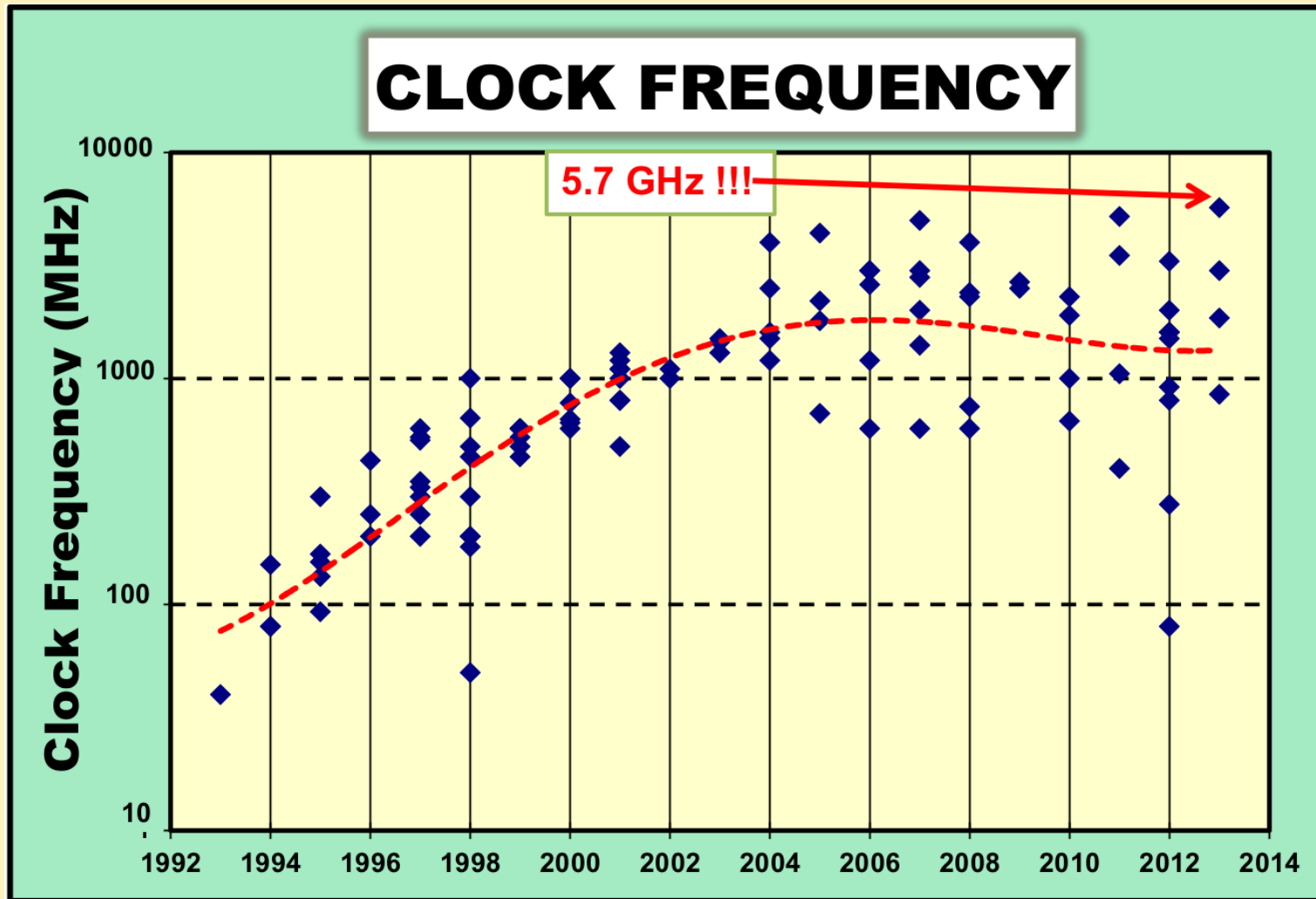
Ron Ho. "On-chip wires: Scaling and efficiency". PhD thesis. Stanford University, 2003

Capacity Trend



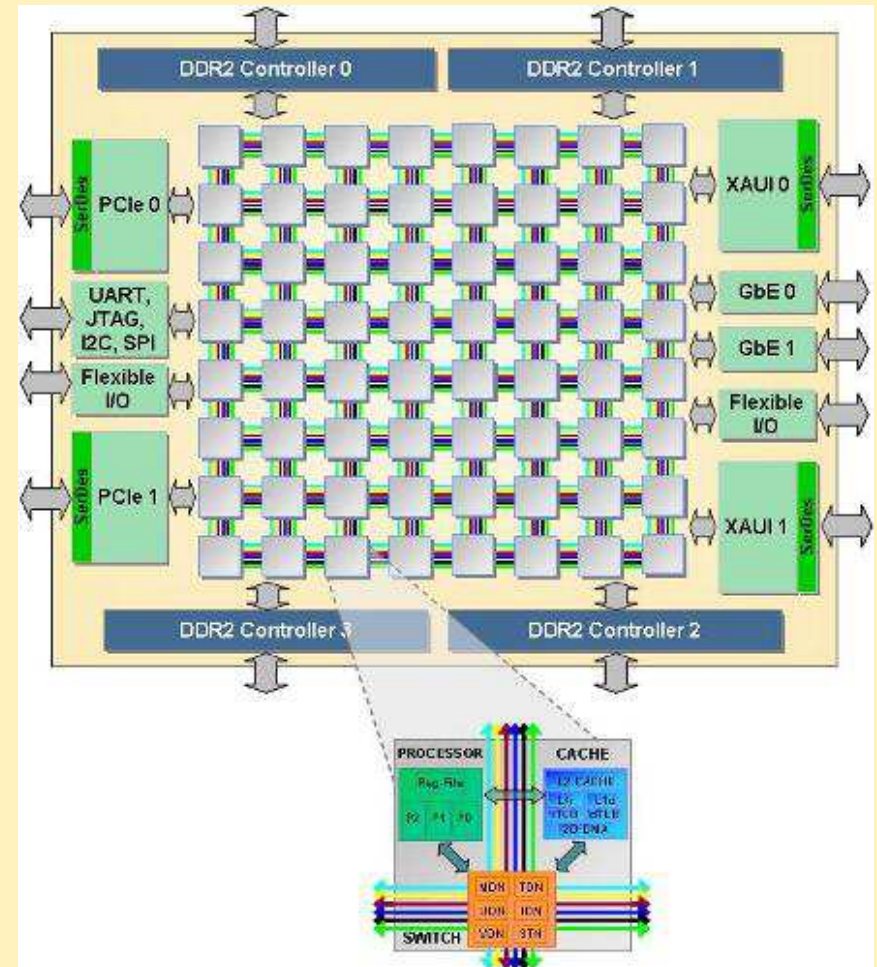
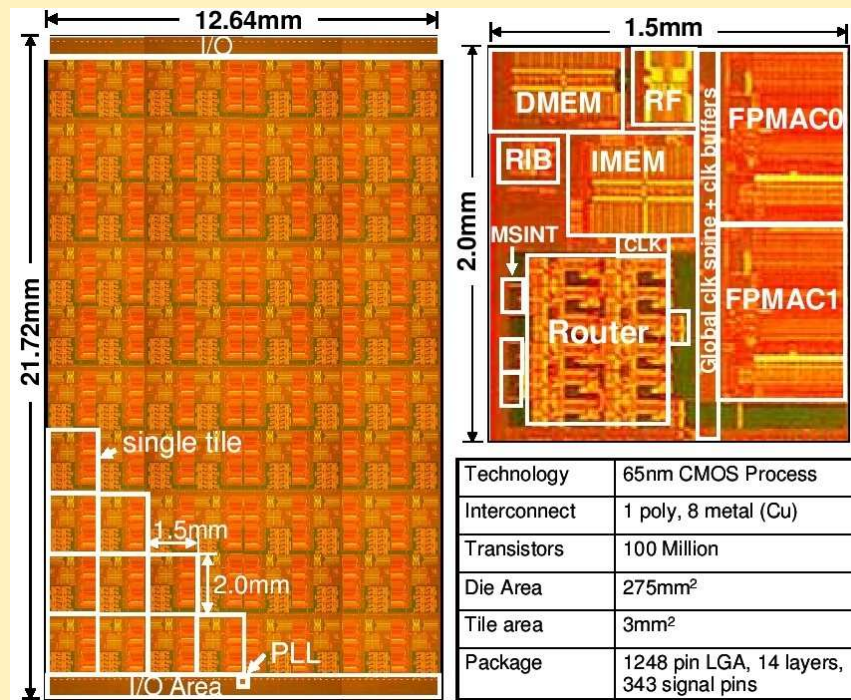
From the ISSCC 2013 Technology Trends

The End of Frequency Scaling

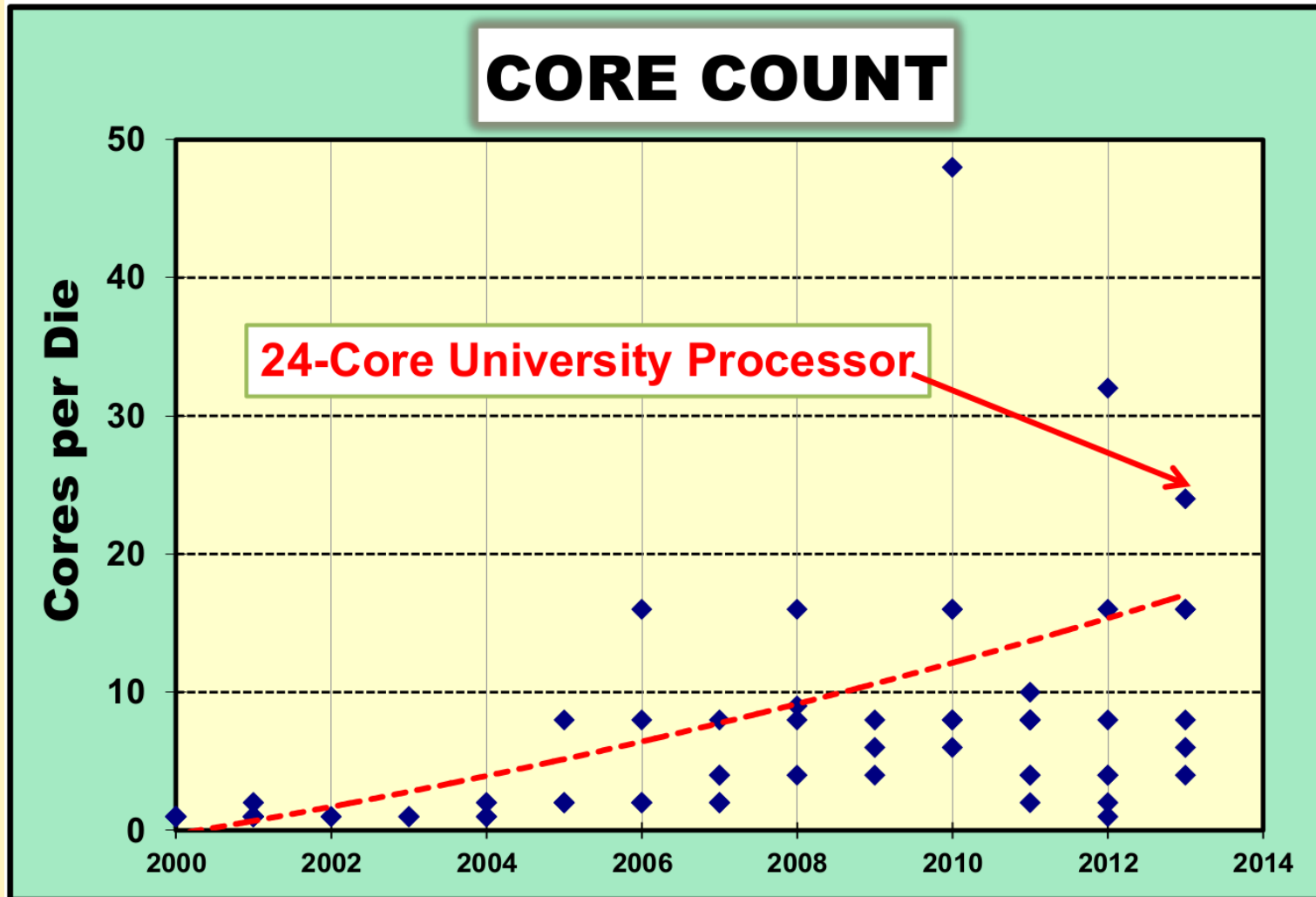


From the ISSCC 2013 Technology Trends

Emergence of NoC

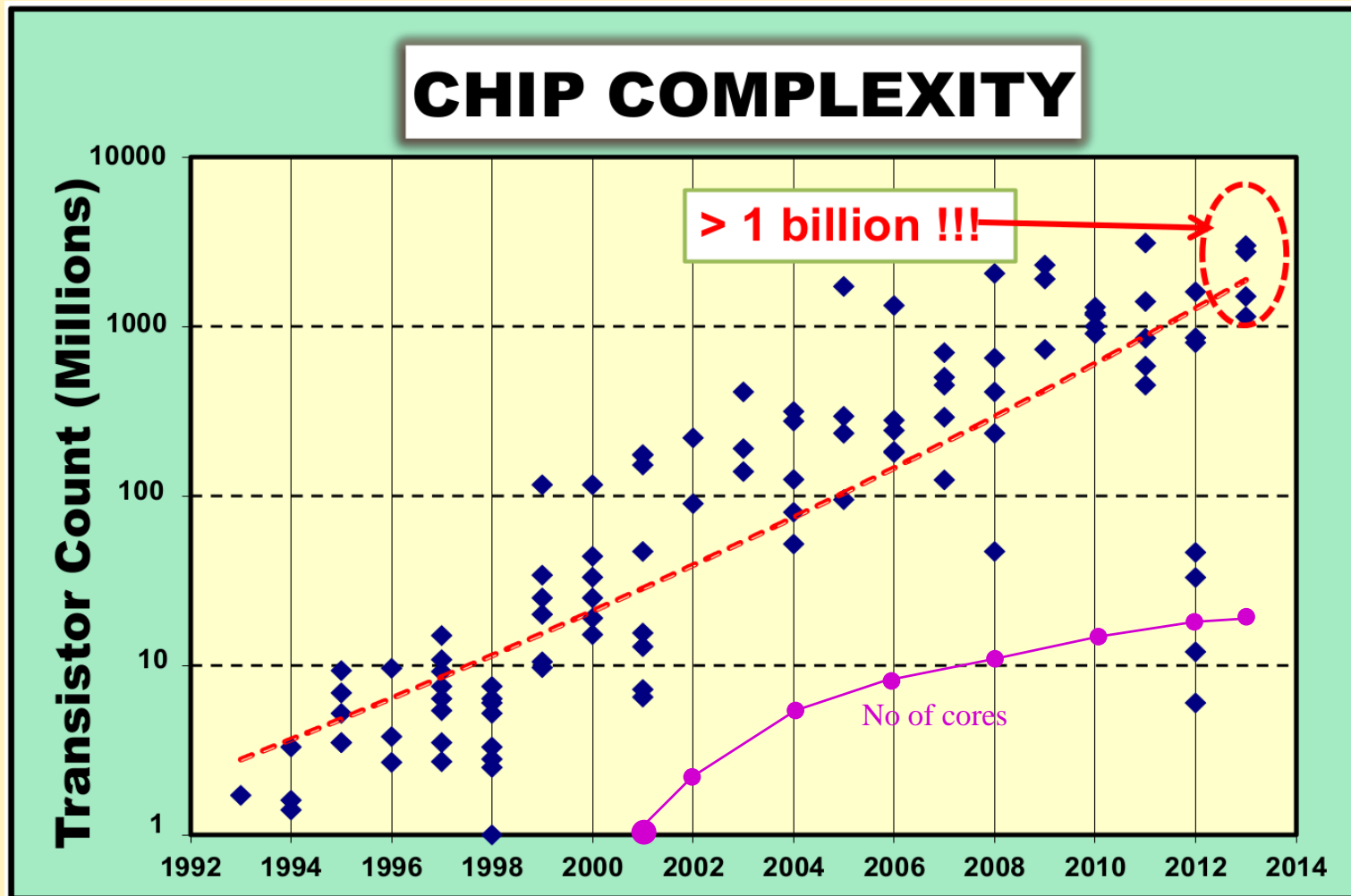


The Multicore Revolution



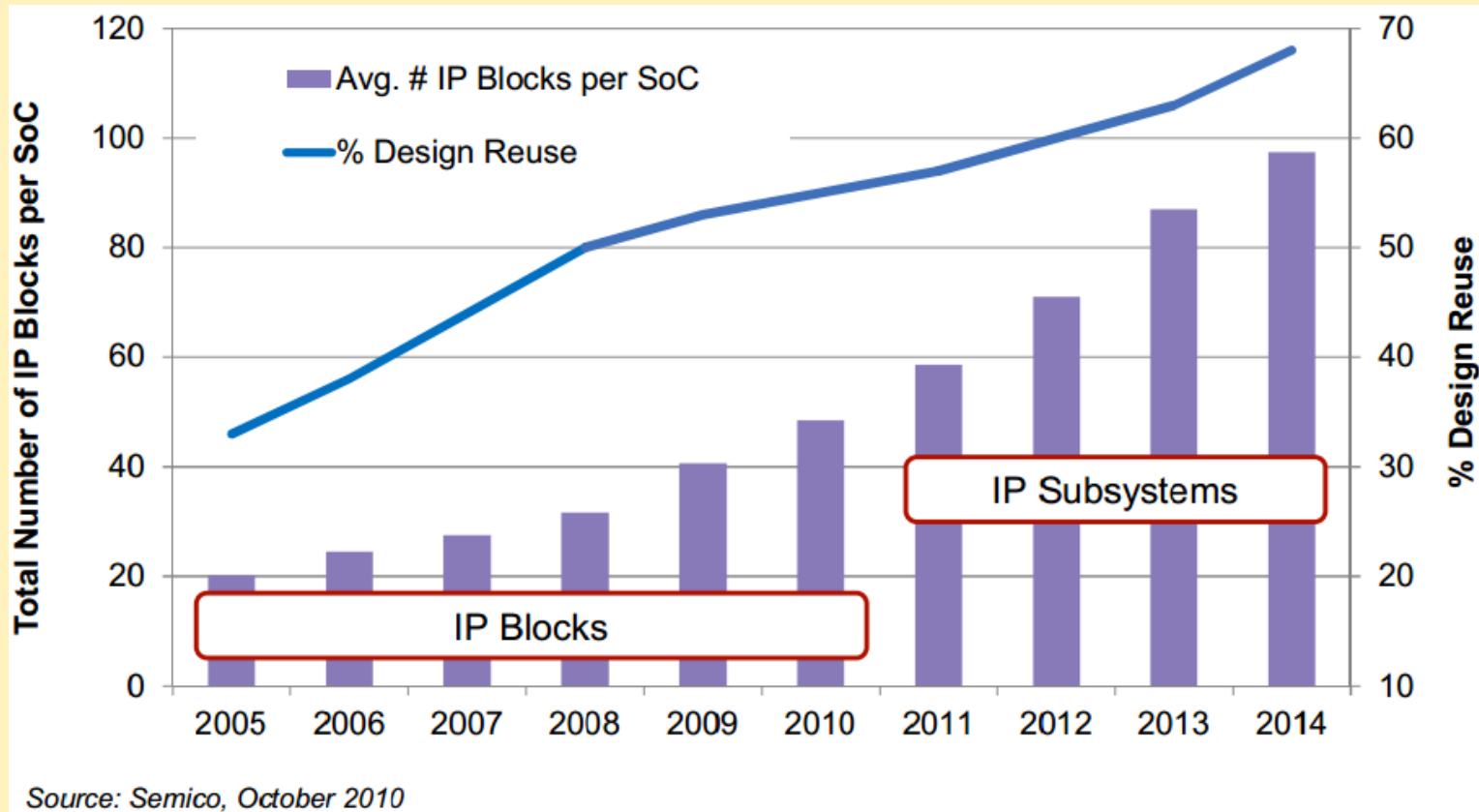
From the ISSCC 2013 Technology Trends

The Multicore Revolution

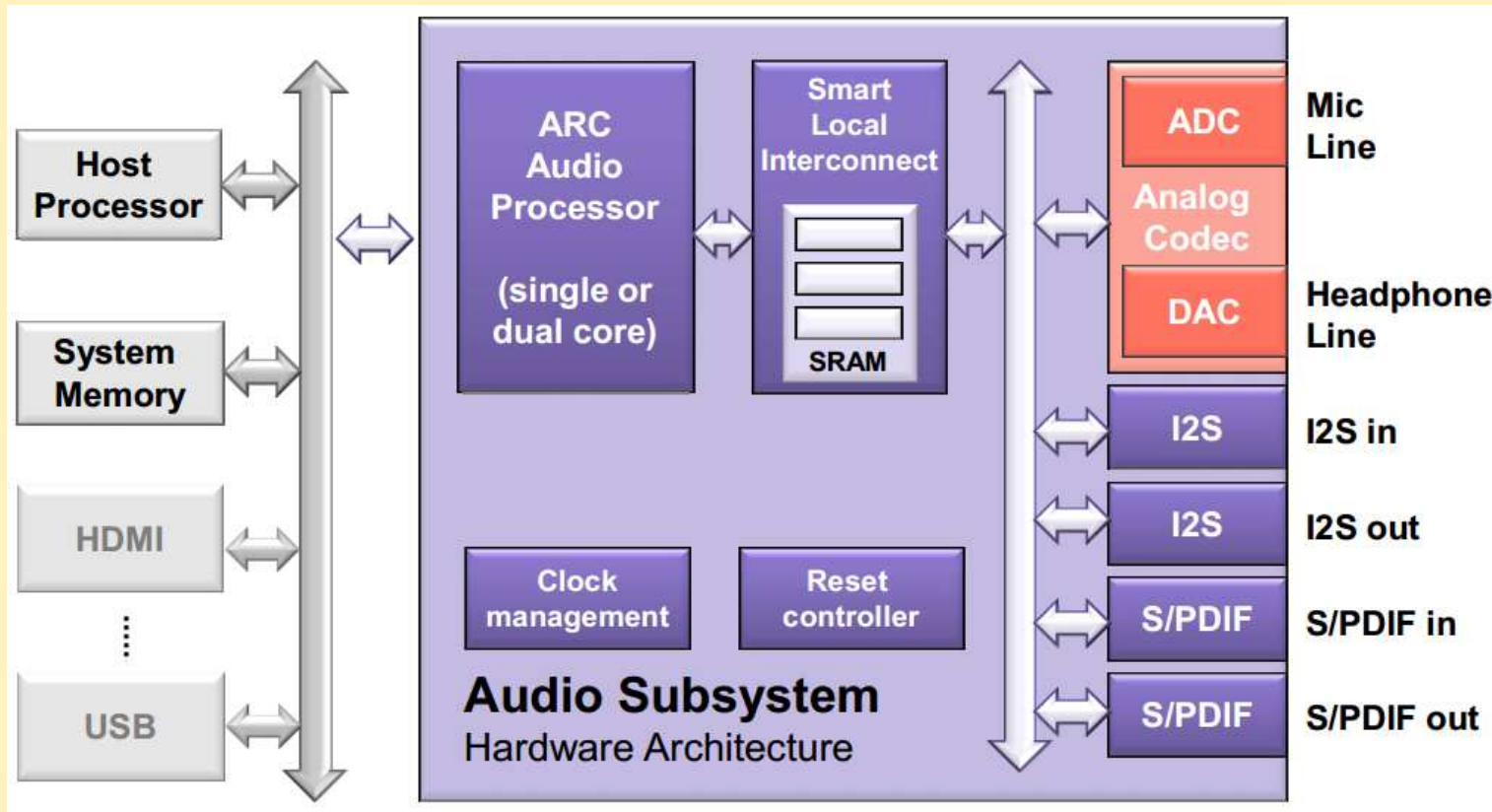


From the ISSCC 2013 Technology Trends

The Reuse of Subsystems



The Reuse of Subsystems



How are Transistors Used?

- More cores and IPs
- SoC infrastructure: interconnect, cache coherence, power management, synchronization, data movement, I/O, test IPs, ...
- Memory, caches, buffers
- IPs become more complex

2013: 3 000 000 000 Transistors

What Next?

2013: 3 000 000 000 Transistors

What Next?

- 22 nm is state of the art
- 14 nm under preparation
- 10 nm is scheduled to go commercial in 2015
- 7 nm is expected in 2020

When Will Moore's Law End?

In 2604

In 2604

Universal Limits on Computation

Lawrence M. Krauss¹ and Glenn D. Starkman^{1,2}

¹ *Center for Education and Research in Cosmology and Astrophysics,
Department of Physics, and Department of Astronomy,
Case Western Reserve University, Cleveland, OH 44106-7079*

² *Department of Physics, CERN, Theory Division, 1211 Geneva 23, Switzerland*

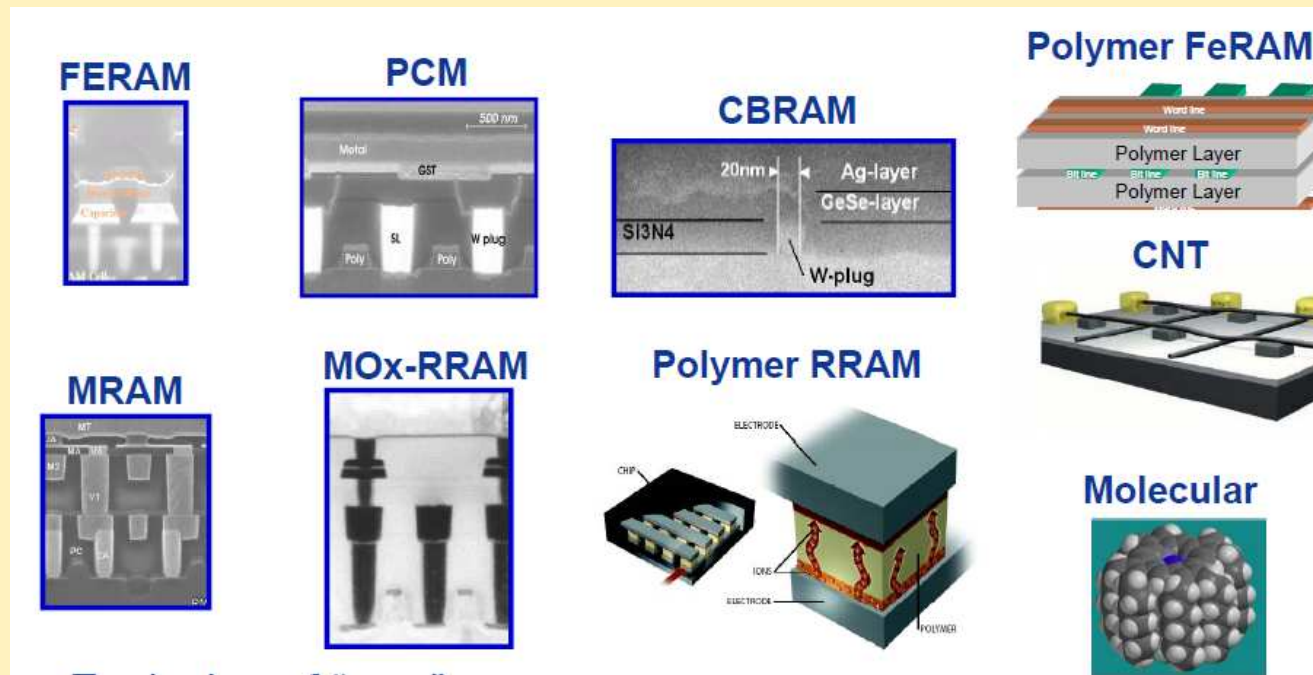
The physical limits to computation have been under active scrutiny over the past decade or two, as theoretical investigations of the possible impact of quantum mechanical processes on computing have begun to make contact with realizable experimental configurations. We demonstrate here that the observed acceleration of the Universe can produce a universal limit on the total amount of information that can be stored and processed in the future, putting an ultimate limit on future technology for any civilization, including a time-limit on Moore's Law. The limits we derive are stringent, and include the possibilities that the computing performed is either distributed or local. A careful consideration of the effect of horizons on information processing is necessary for this analysis, which suggests that the total amount of information that can be processed by any observer is significantly less than the Hawking-Bekenstein entropy associated with the existence of an event horizon in an accelerating universe.

Trends

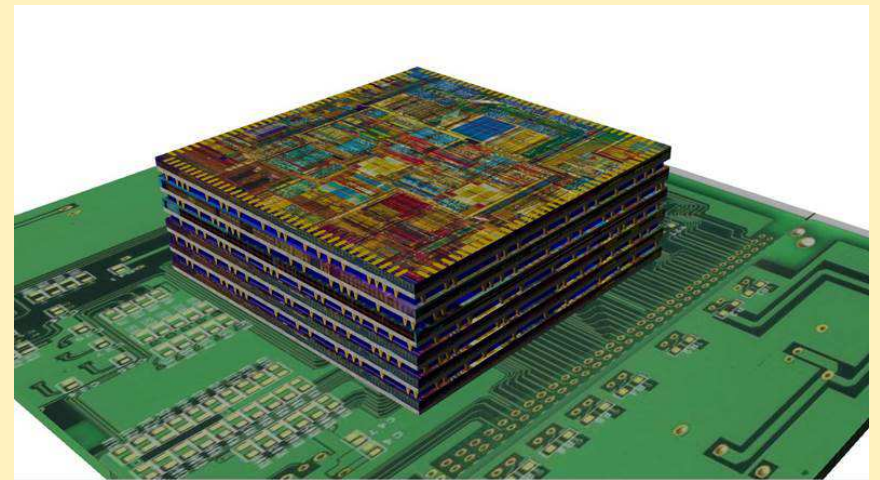
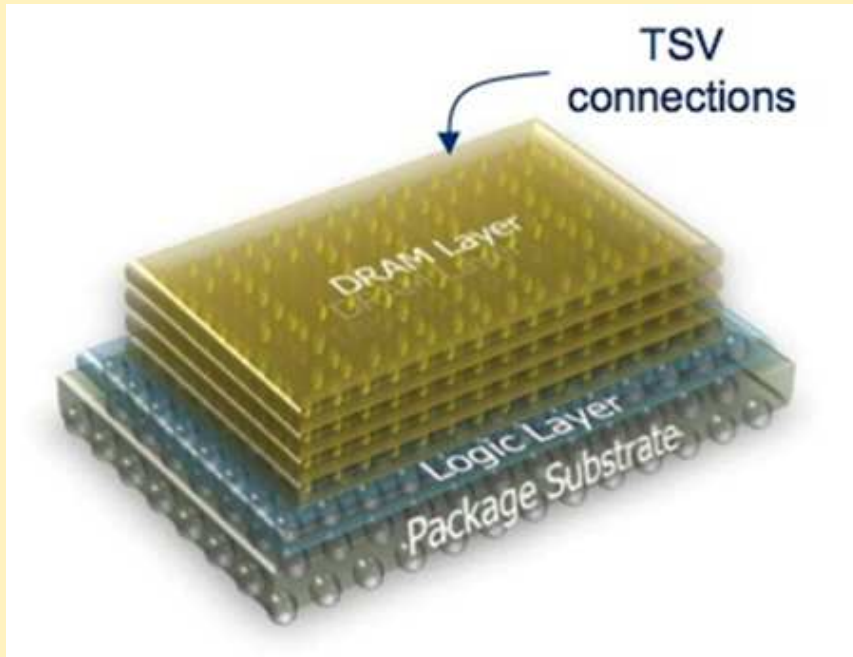
- Many new technologies under development
- Heterogeneity and Specialization
- Integration with the physical world

Promising Technologies

- 3D Stacking
- 3D Transistors
- Phase Change RAM
- Spin Torque Transfer RAM
- Memristor
- Hybrid Memory Architectures
- Carbon Nano Tubes
- Organic Electronics
- Functional Materials
- ...



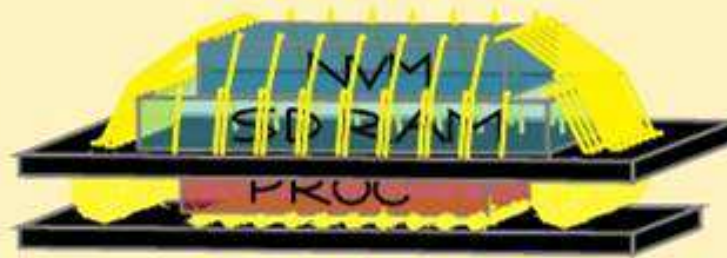
3D Stacking



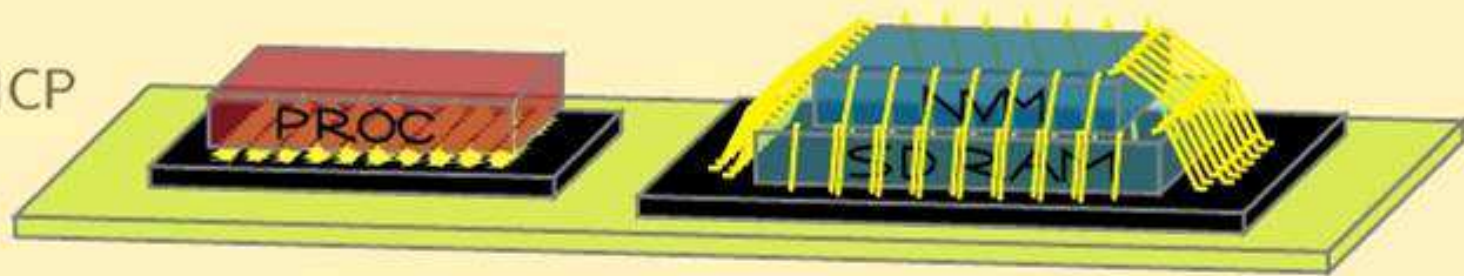
3D Stacking



POP with Stacked MCP



Stacked MCP

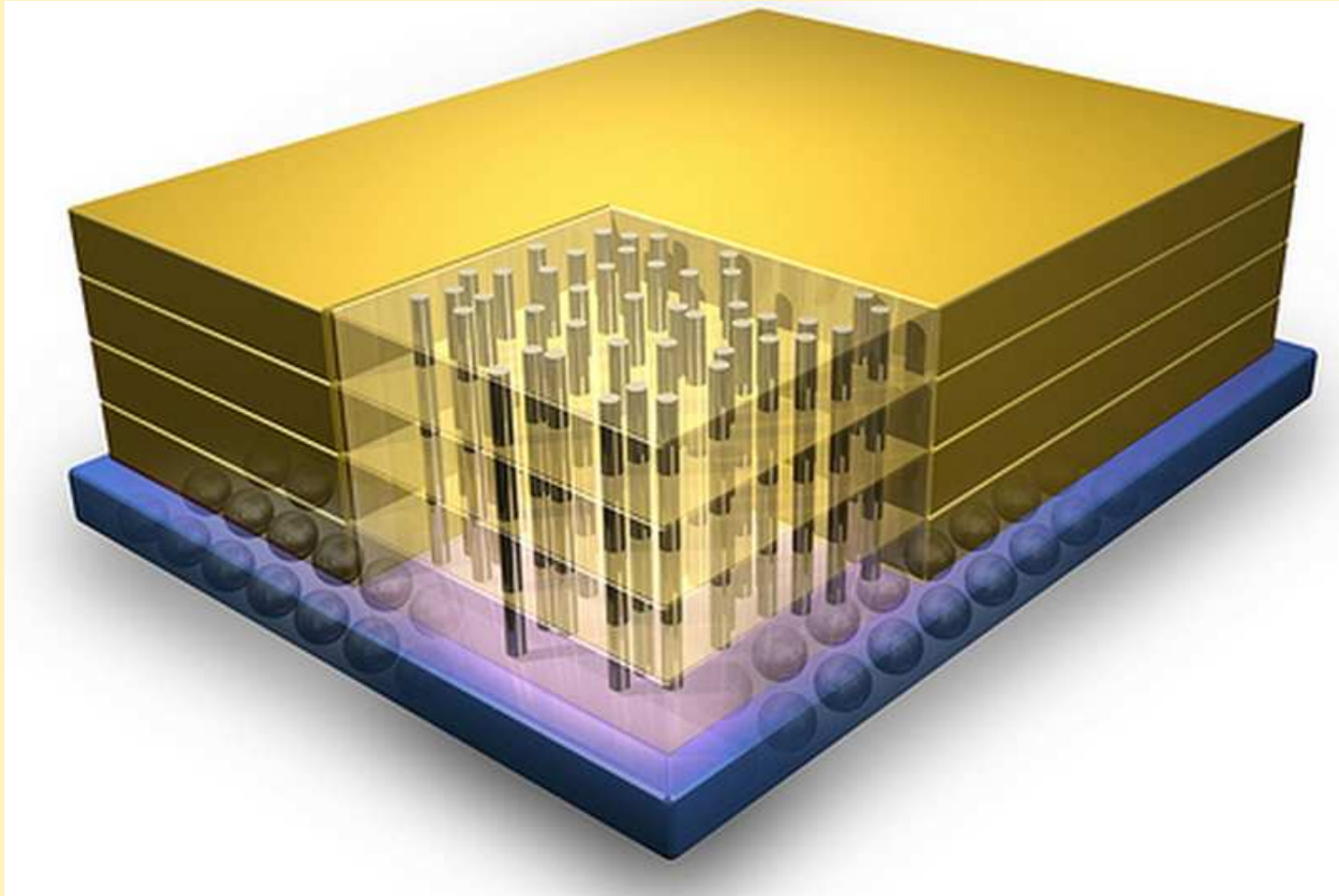


Off-Package



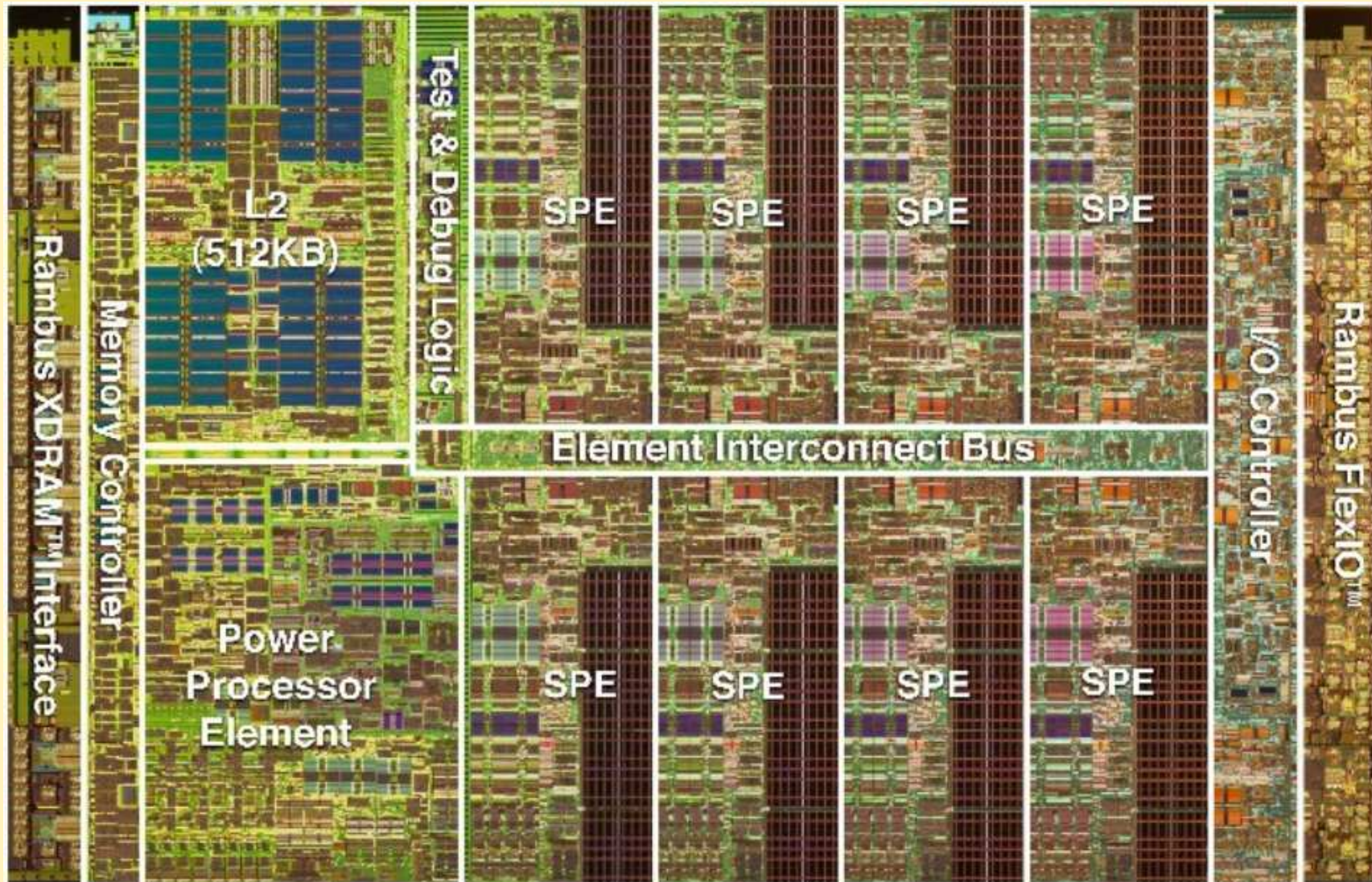
From: Denis Dutois and Ahmed Jerraya. "3D Integration Opportunities for Memory Interconnect in Mobile Computing Architectures". In: *Future Fab International* 34 (July 2010)

3D Stacking



Micron 2014: 4 GB package, 4 dies stacked in a $31 \times 31\text{mm}^2$ package

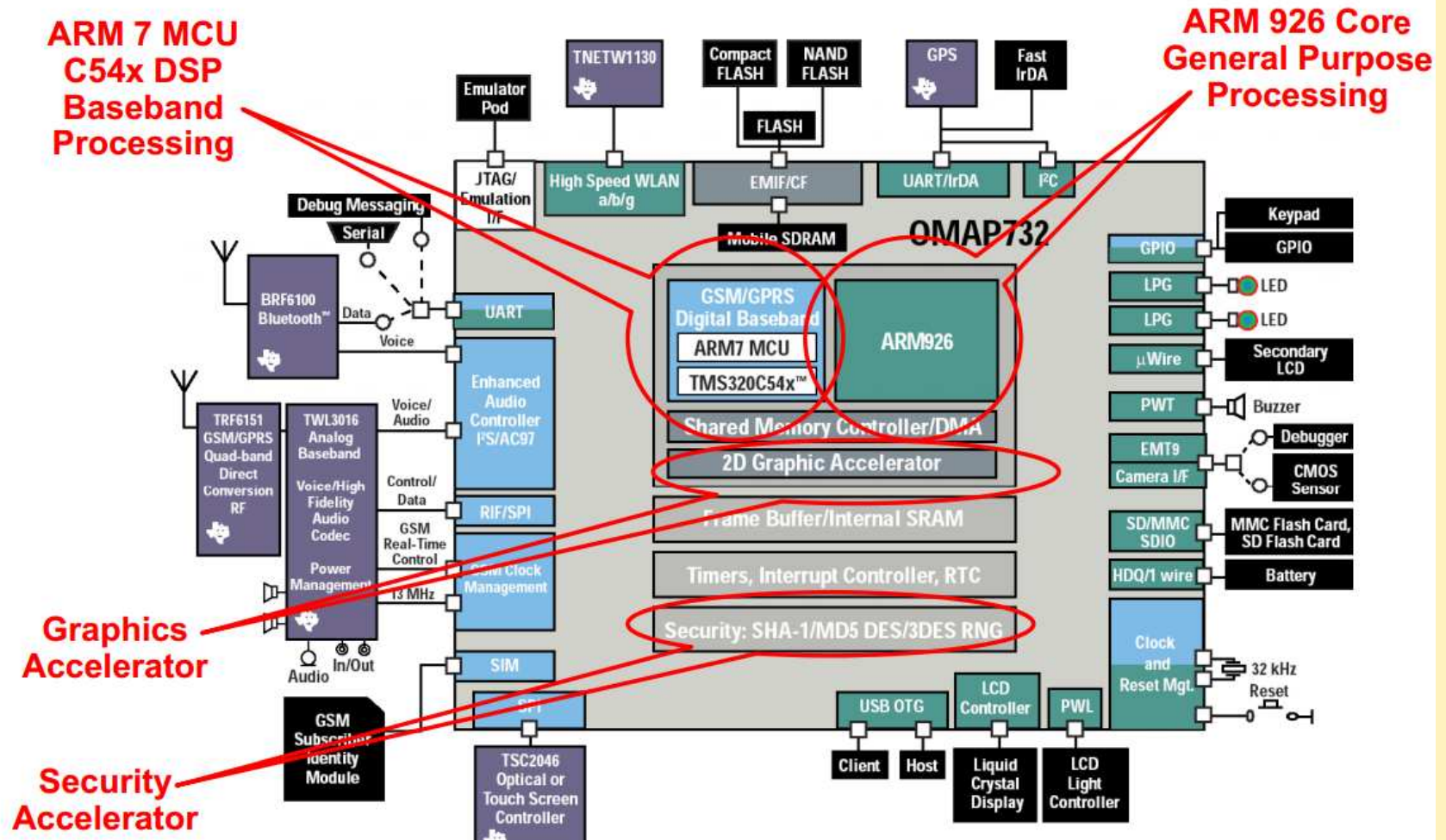
The Era of Heterogeneity



IBM Cell Processor

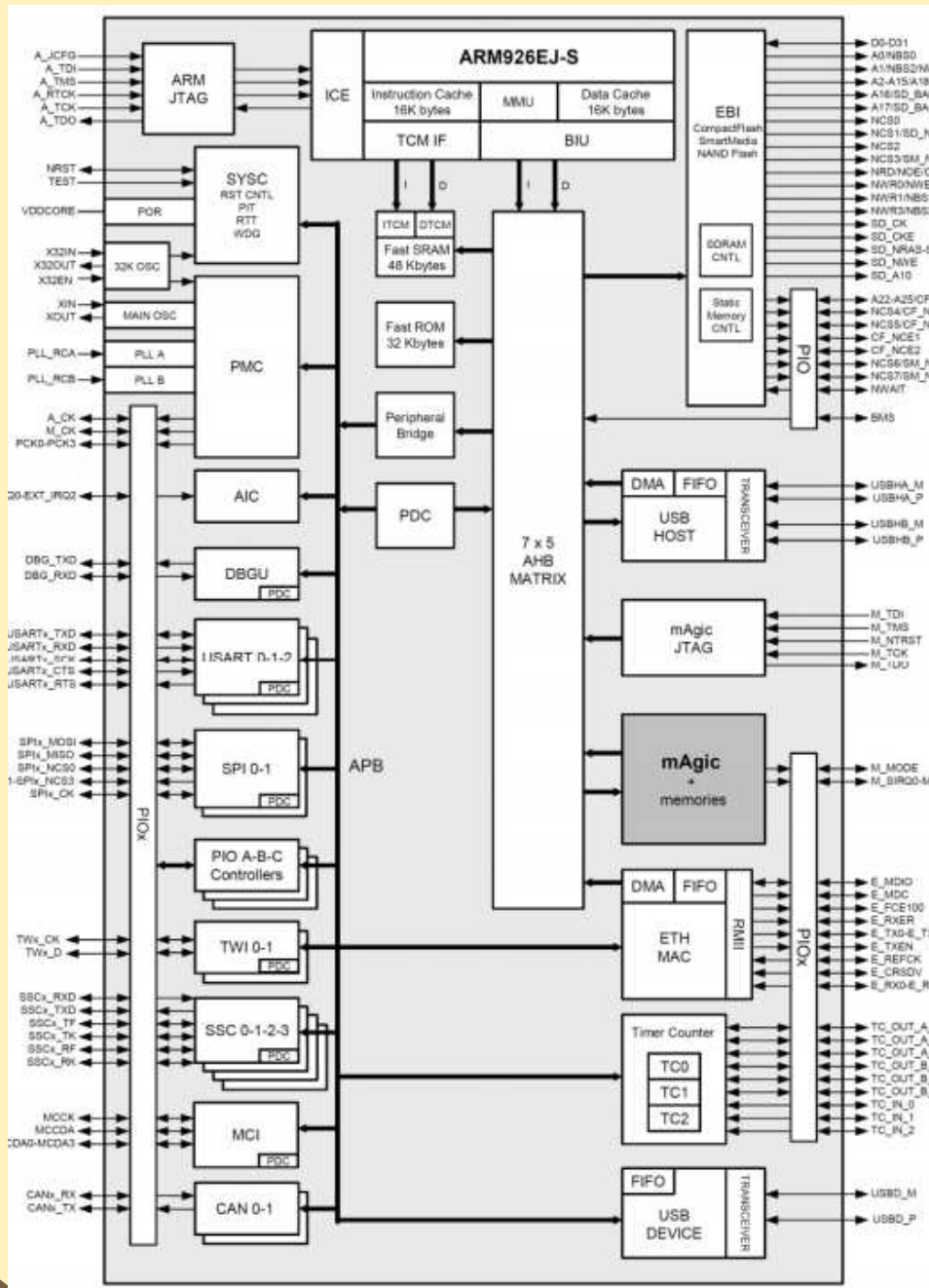
The Era of Heterogeneity

TI OMAP732 Hardware Platform



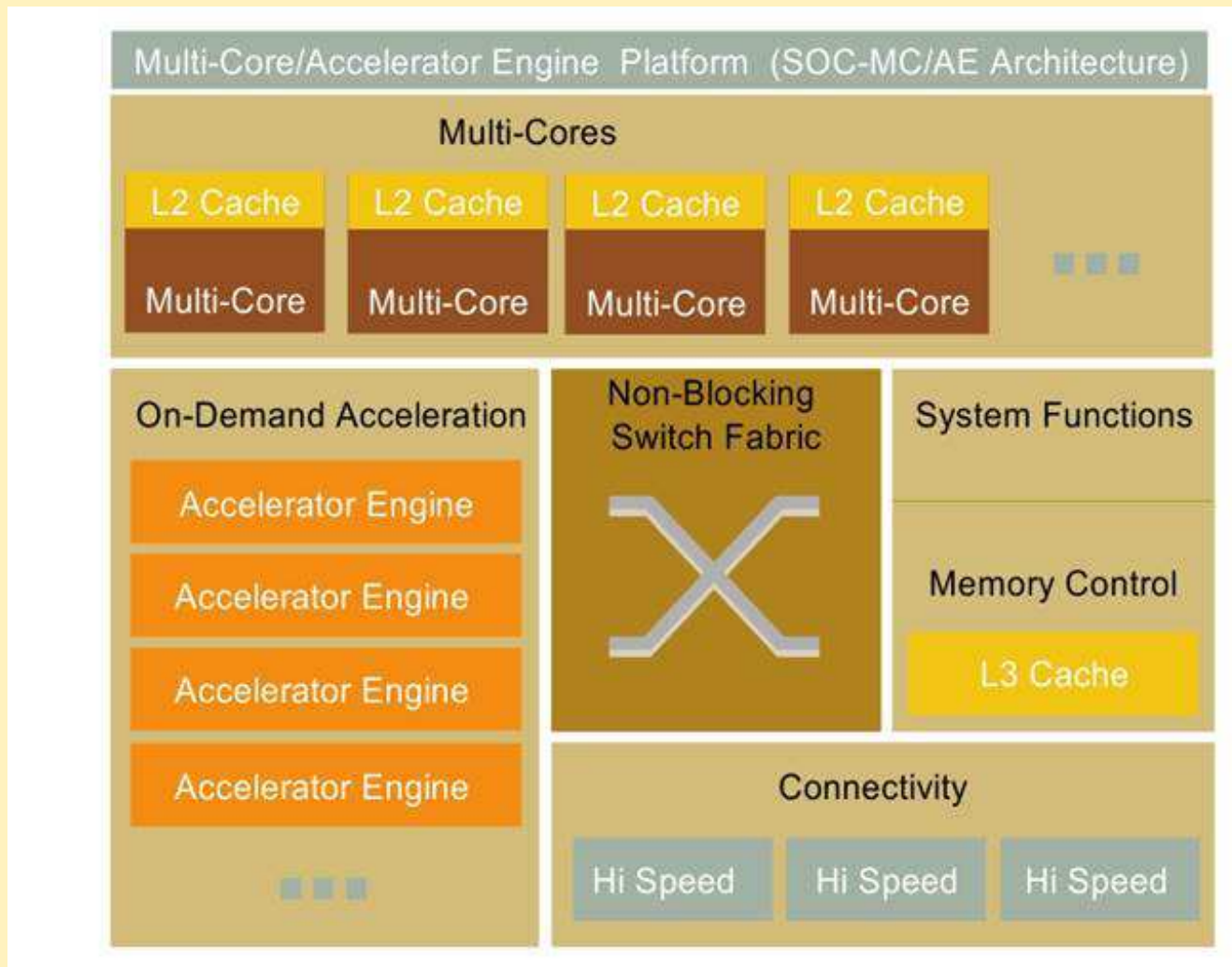
TI OMAP Platform

The Era of Heterogeneity



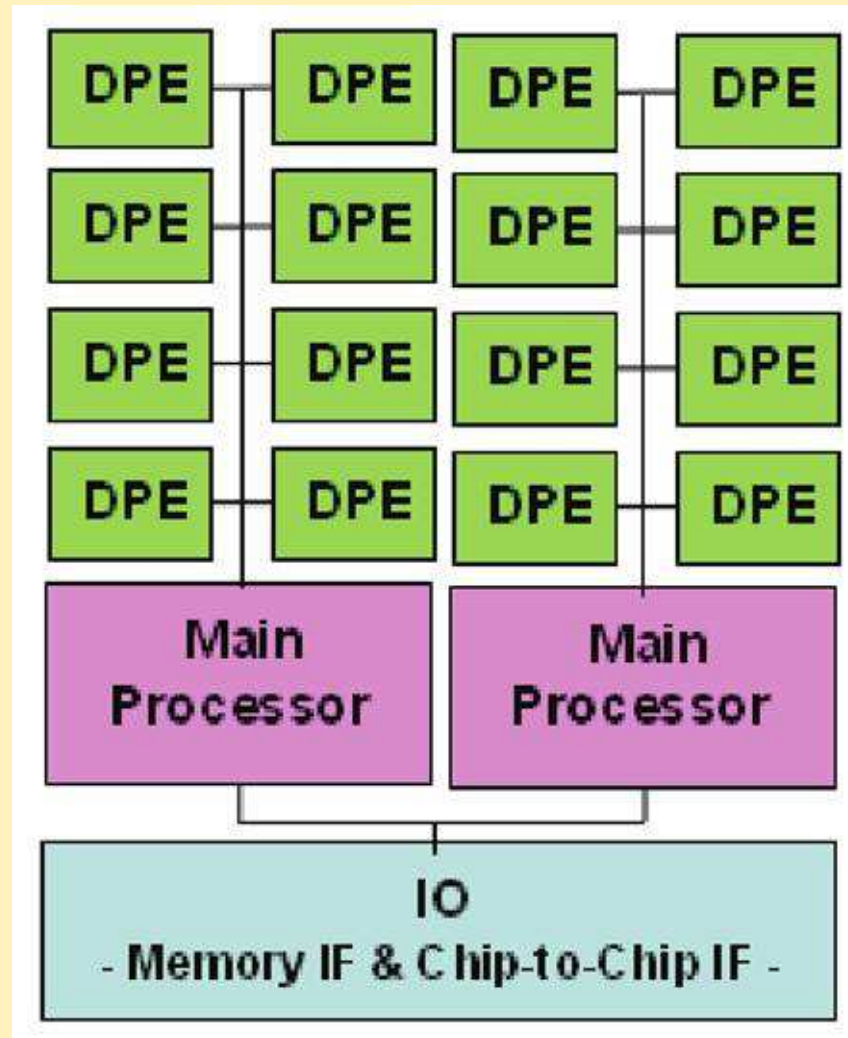
DIOPSIS 940 for audio, speech processing, automotive sound, robotics

The Era of Heterogeneity



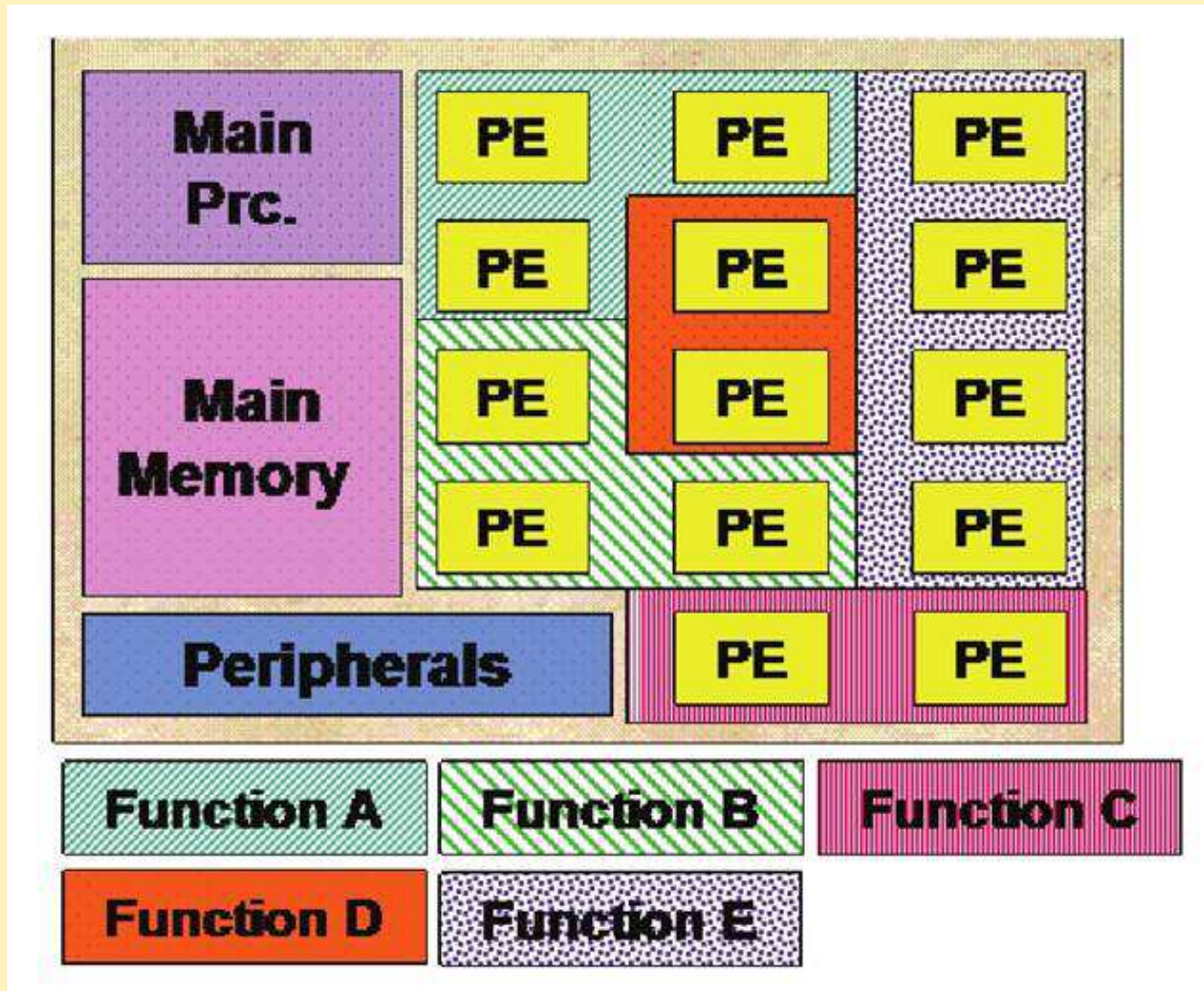
SoC Networking Architecture (ITRS)

The Era of Heterogeneity



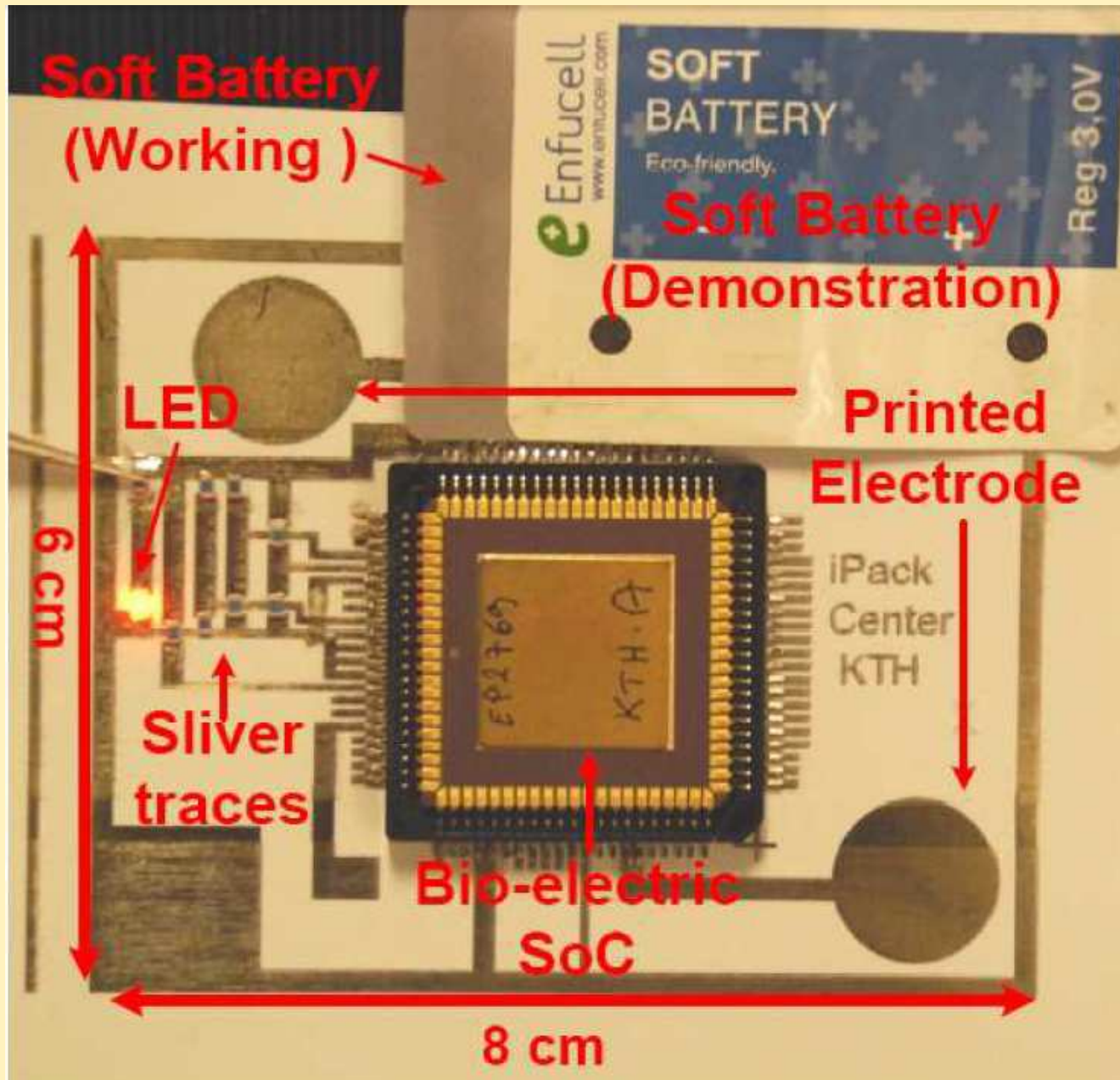
SoC Consumer Stationary (ITRS)

The Era of Heterogeneity

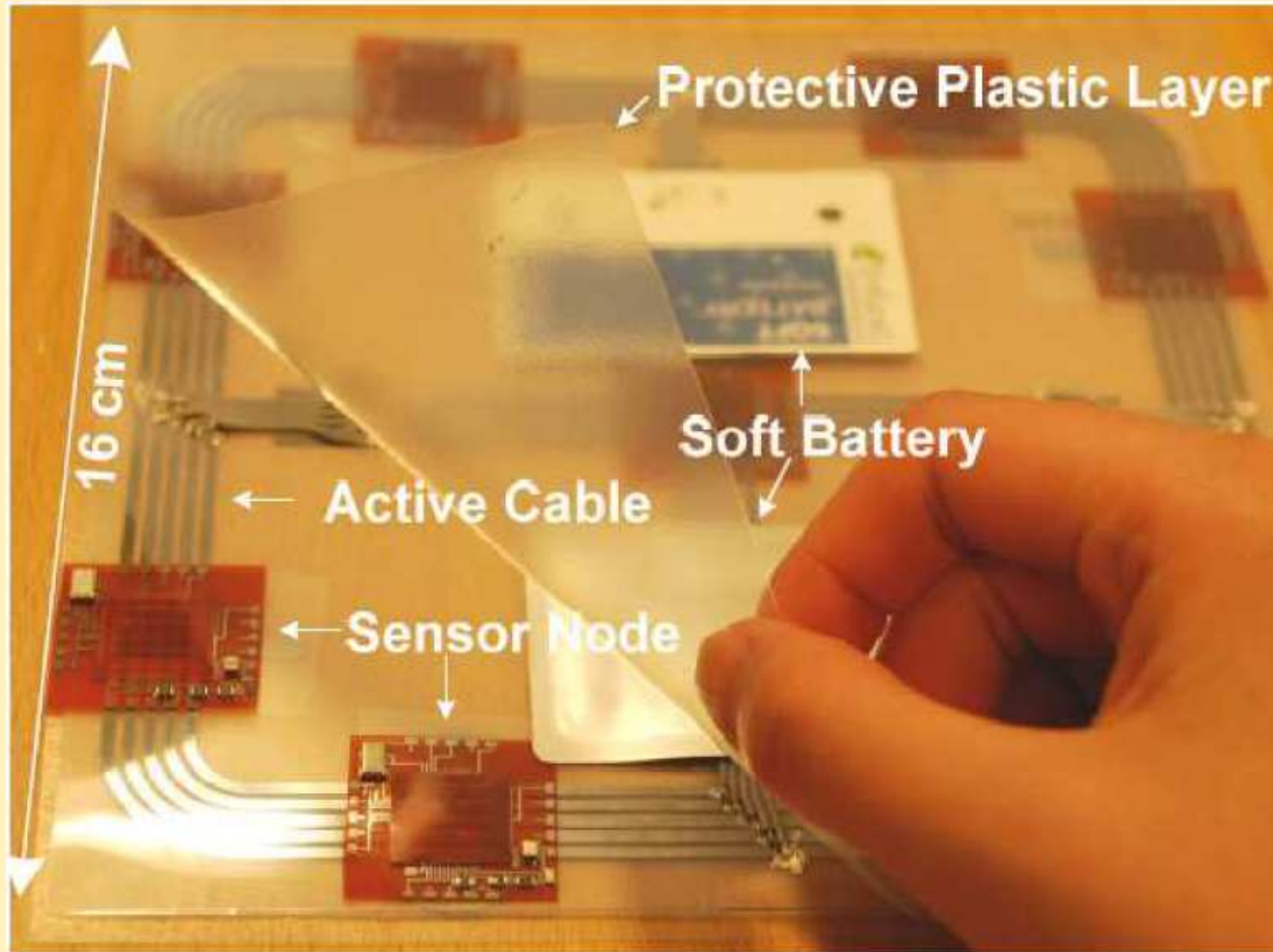


SoC Consumer Portable (ITRS)

Heterogeneous Integration

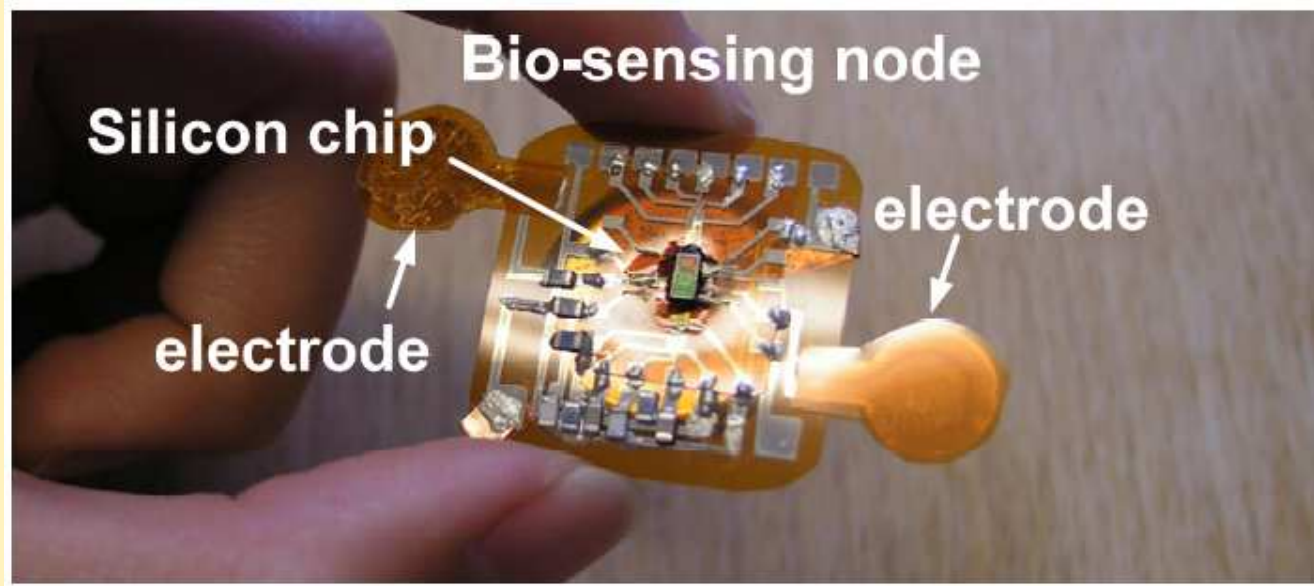


Heterogeneous Integration



Courtesy of KTH

Heterogeneous Integration



Courtesy of KTH

Lighting Control



Courtesy of MIT Media Lab

Eyesight Test



Courtesy of MIT Media Lab

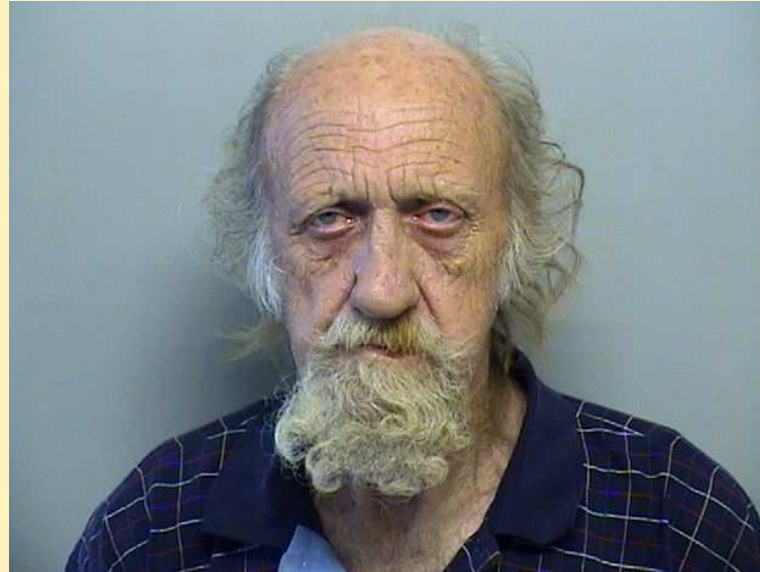
Non-Invasive Monitoring



Courtesy of MIT Media Lab

The World in 2025

The World in 2025



The World in 2025

- Moore's Law has faded away

The World in 2025

- Moore's Law has faded away
- General purpose computing has become a niche market

The World in 2025

- Moore's Law has faded away
- General purpose computing has become a niche market
- We have a wealth of materials and technologies at hand

The World in 2025

- Moore's Law has faded away
- General purpose computing has become a niche market
- We have a wealth of materials and technologies at hand
- New value comes from
 1. **Devising new solutions to interesting problems**
 2. Novel, heterogeneous integration
 3. New sensors and actuators
 4. New materials including bio-processes
 5. Further IC integration